

Cristian Pira

On behalf of INFN LNL SRF group



i.FAST has received funding from the European Union's
Horizon 2020 programme under GA No 101004730.



Nb₃Sn on Cu coating by Magnetron Sputtering from Target Synthesized via Liquid Tin Diffusion

TESLA TECHNOLOGY
TTC
COLLABORATION

Aomori
October 11-14, 2022



Outline

- **Project goal** and motivations
- Liquid Tin Diffusion **technique introduction**
- Target production **first results**
- First **sputtering test** with LTD target

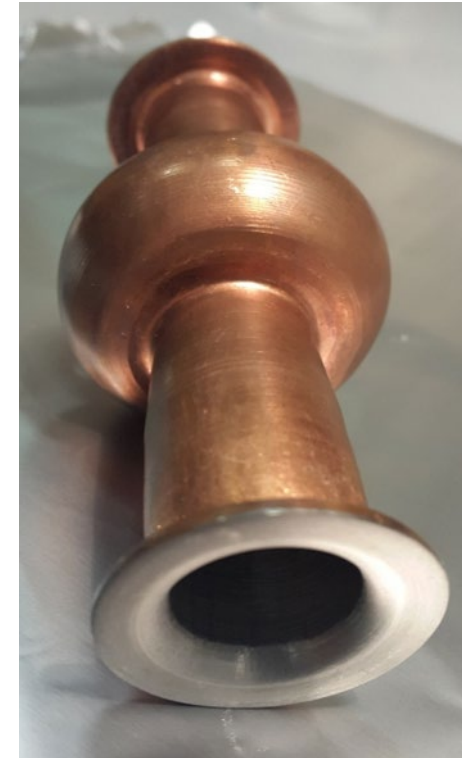
Goal and motivations

Goal

Produce and test a
Nb₃Sn on Cu
6 GHz elliptical cavity

Motivations:

- **Cu** is a **cheaper** substrate
- Higher **thermal conductivity**
(important also for applications beyond high energy physics with cryocooler cooling)
- **6 GHz** are a good test bench
(handable, cheap, fast to test, test facility ready @LNL)



Nb on Cu 6 GHz cavity

LNL Strategy

Use the **same Magnetron Sputtering configuration** of **Nb on Cu**
6 GHz elliptical cavity

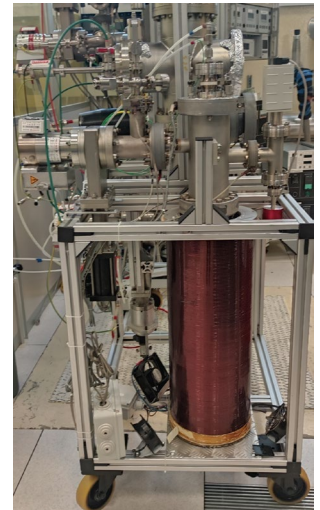
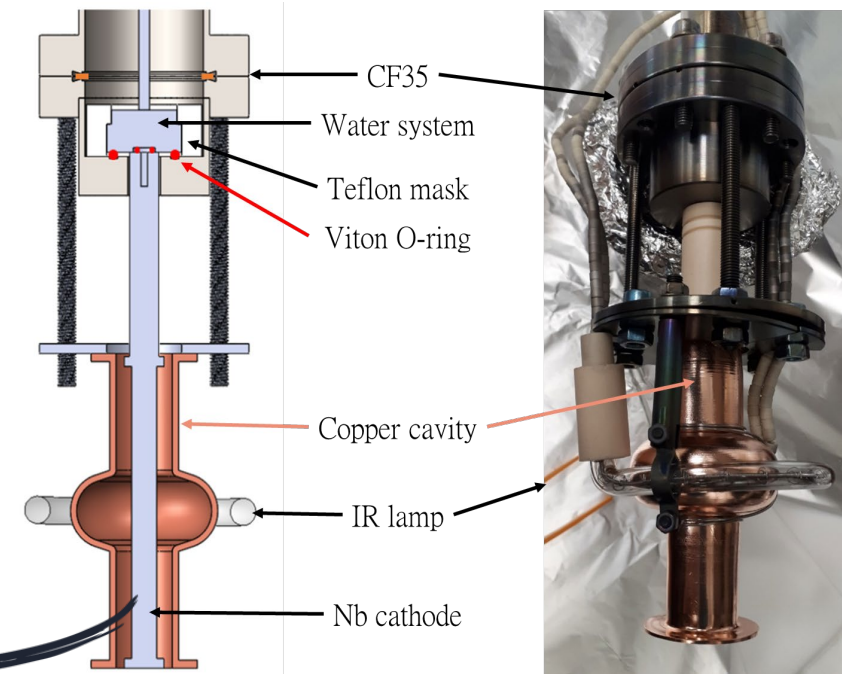


Replace Nb cylindrical target with a Nb₃Sn one

Not so easy because
Nb₃Sn is extremely brittle!

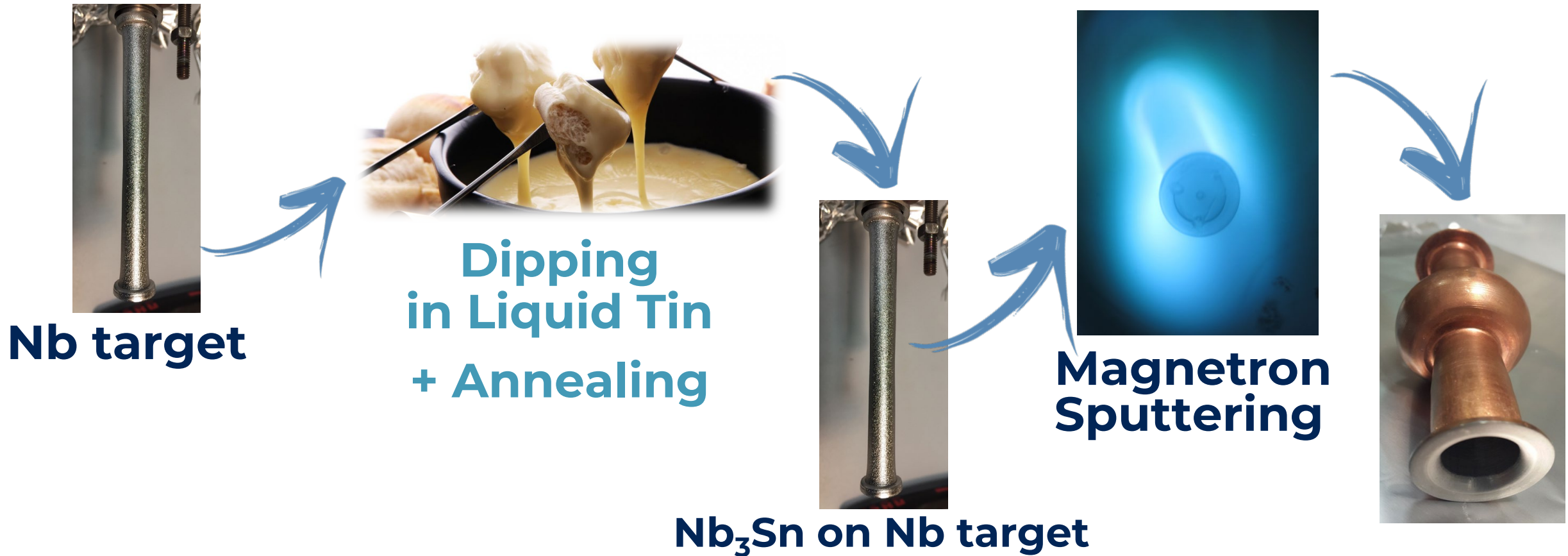
Sintered bulk target cannot be used

Nb on Cu 6 GHz cavity coating system



Nb₃Sn on Cu

LNL strategy for 6 GHz cavities



Liquid Tin Diffusion

in a couple of slides...

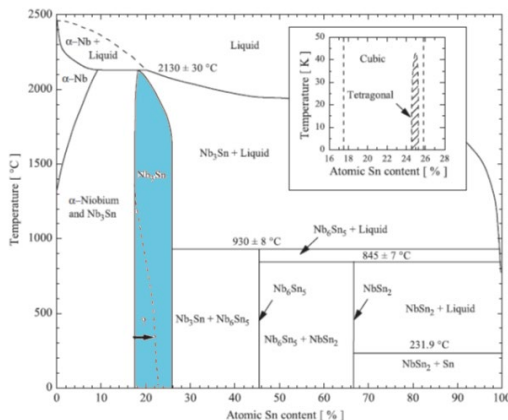
Vapor or Liquid Tin Diffusion



Tin Vapor Diffusion

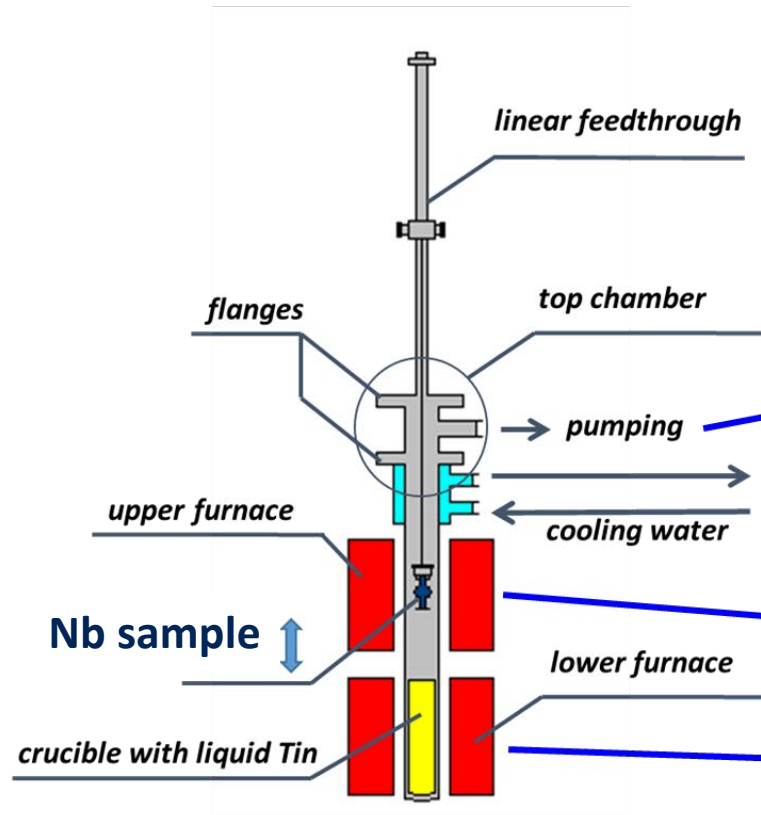


Liquid Tin Diffusion
(Dipping)



- **Similar principle:** Sn diffuse onto Nb and react at High T
- Both suitable to growth **Nb_3Sn films on Nb substrates**
- Liquid Tin diffusion allows coating of **thick films**

Liquid Tin Diffusion Set Up @ INFN LNL



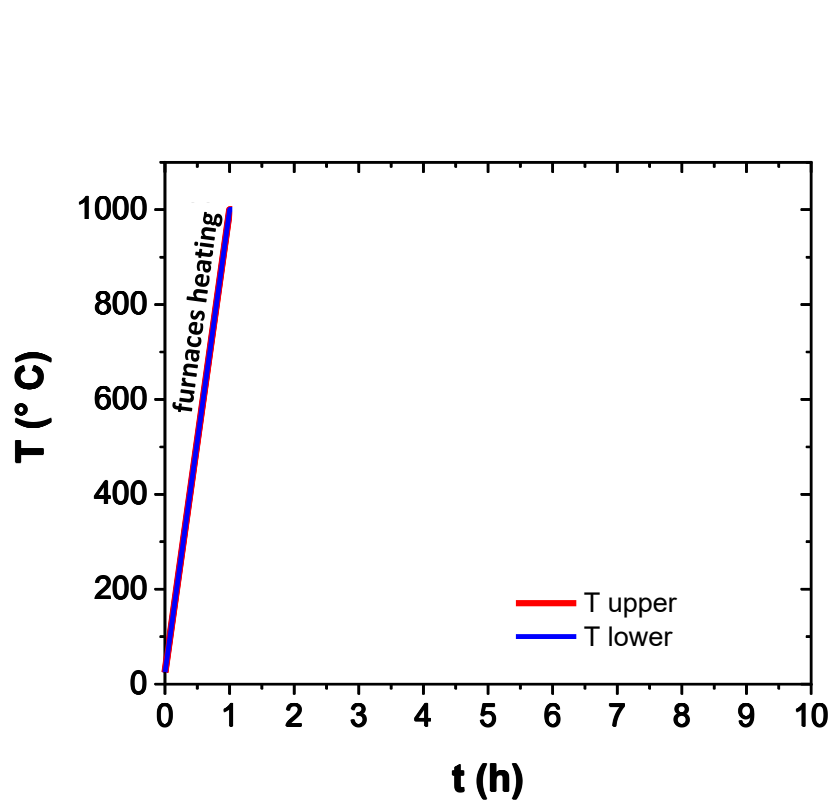
System **designed in 2005** for the coating of 6 GHz elliptical cavities

UHV Inconel chamber

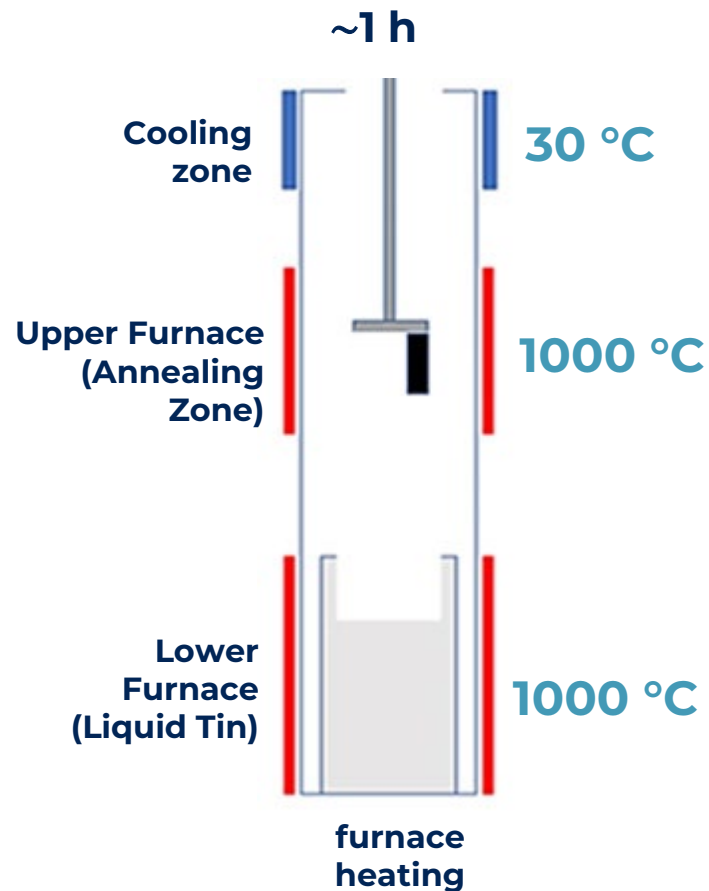
2 Separate **resistive furnaces**

Dipping process (LNL 2006)

S. M. Deambrosis et al., "A15 superconductors: An alternative to niobium for RF cavities," Physica C, 2006



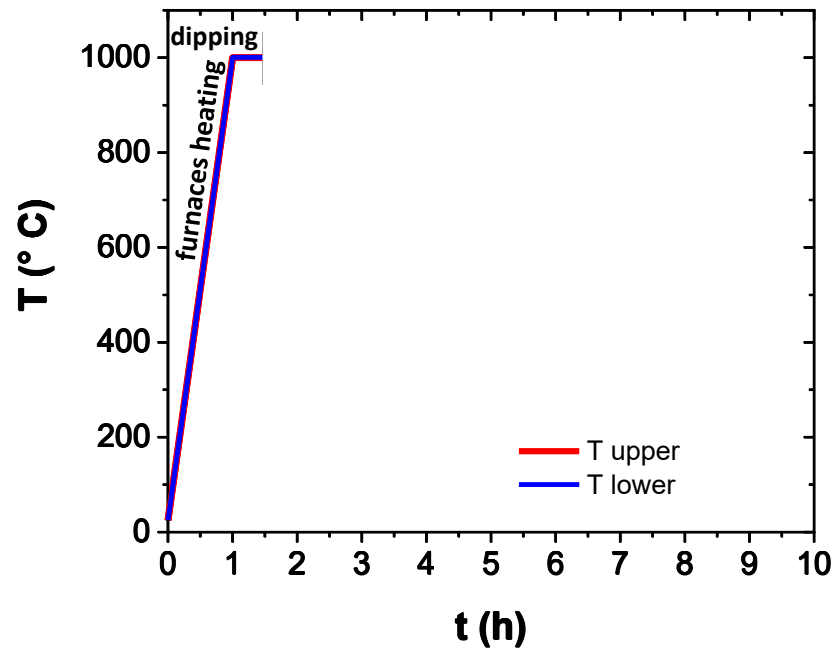
Temperature furnaces profile



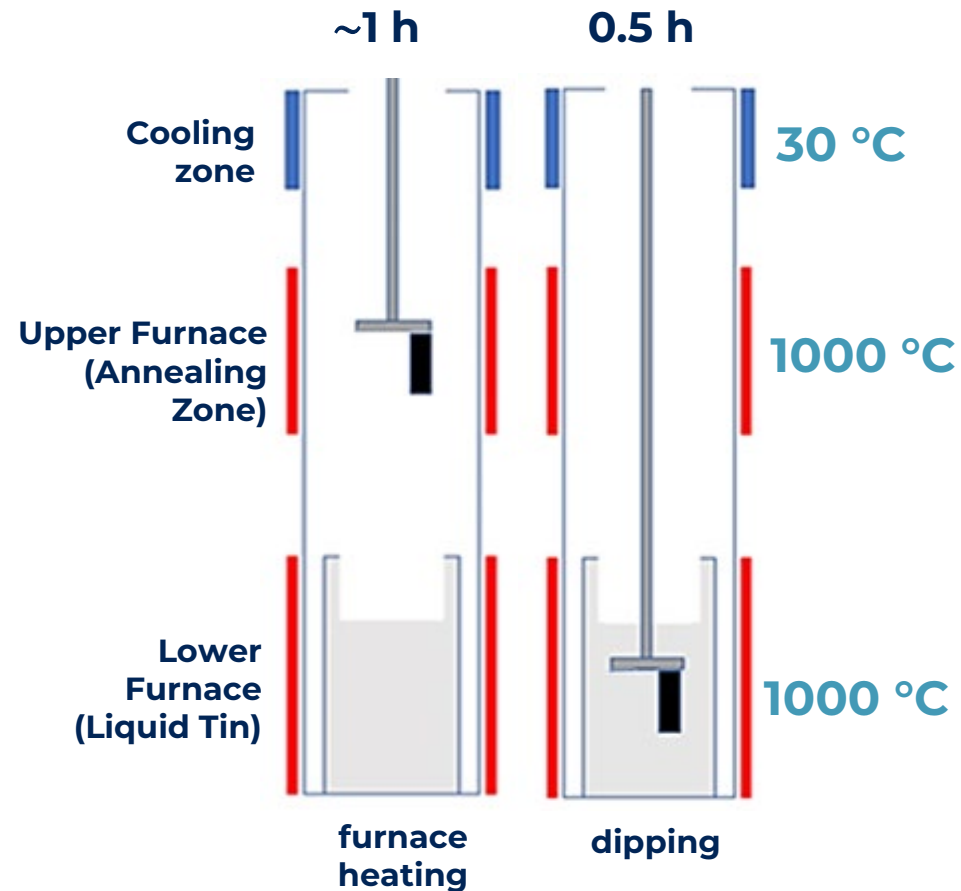
Sample temperature
 $\Delta T \sim -100-150 ^{\circ}\text{C}$

Dipping process (LNL 2006)

S. M. Deambrosis et al., "Al₅ superconductors: An alternative to niobium for RF cavities," Physica C, 2006

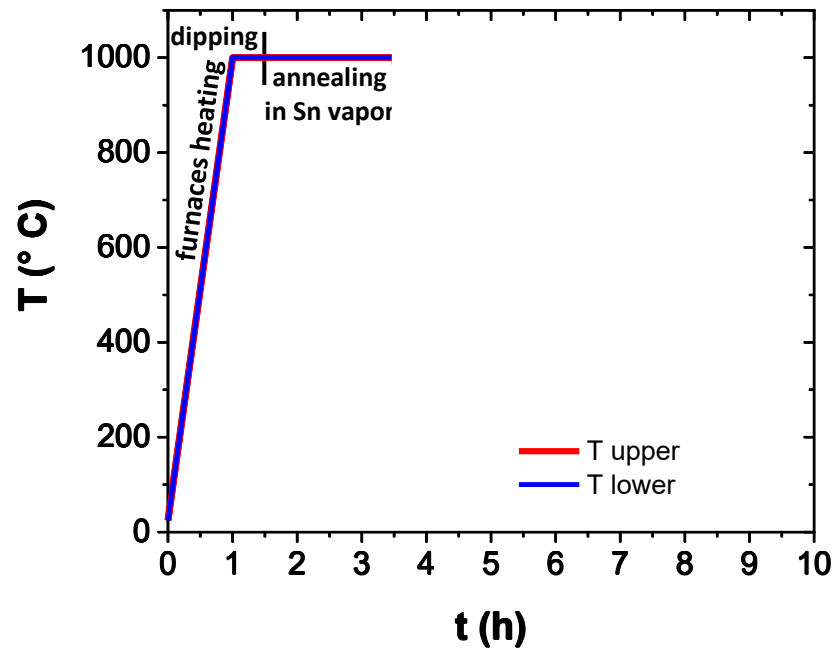


Temperature furnaces profile

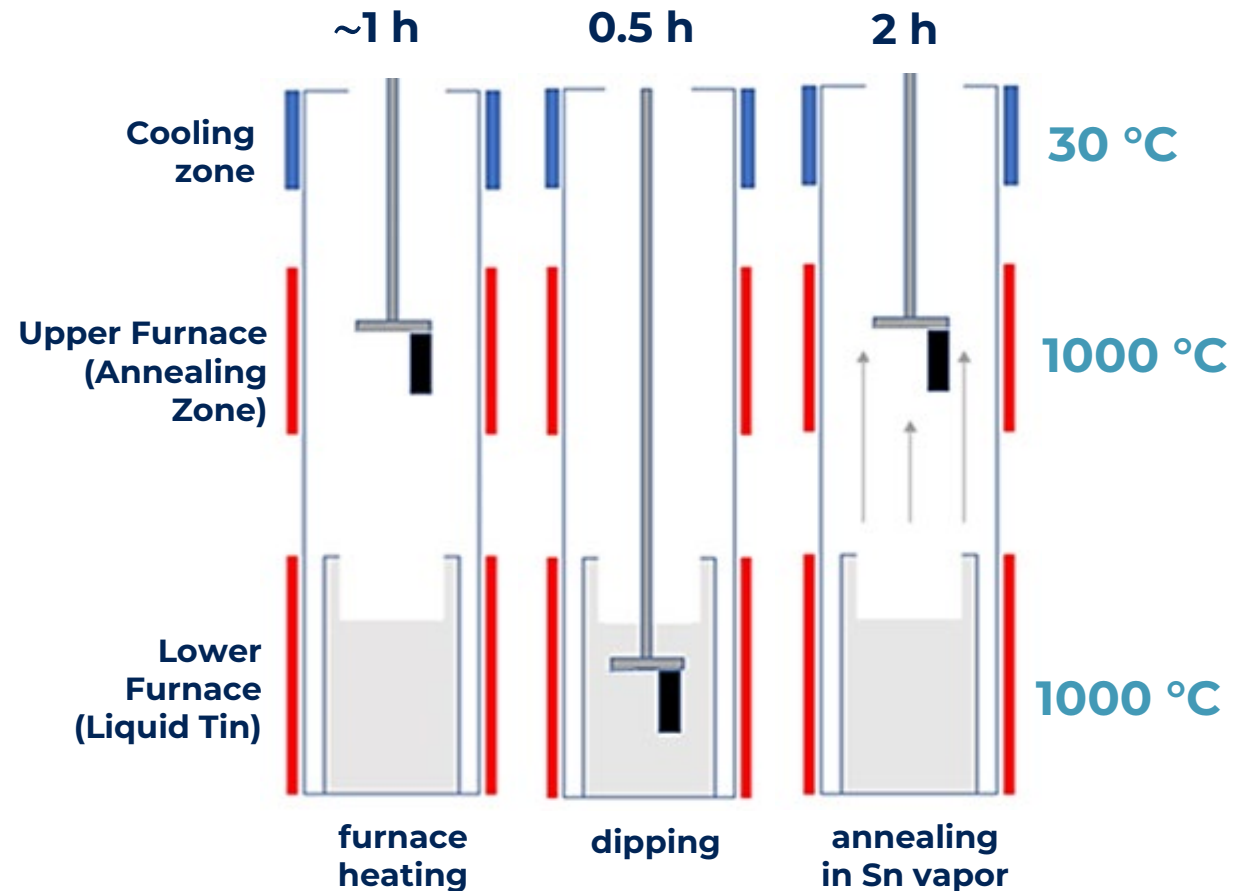


Dipping process (LNL 2006)

S. M. Deambrosis et al., "A15 superconductors: An alternative to niobium for RF cavities," *Physica C*, 2006

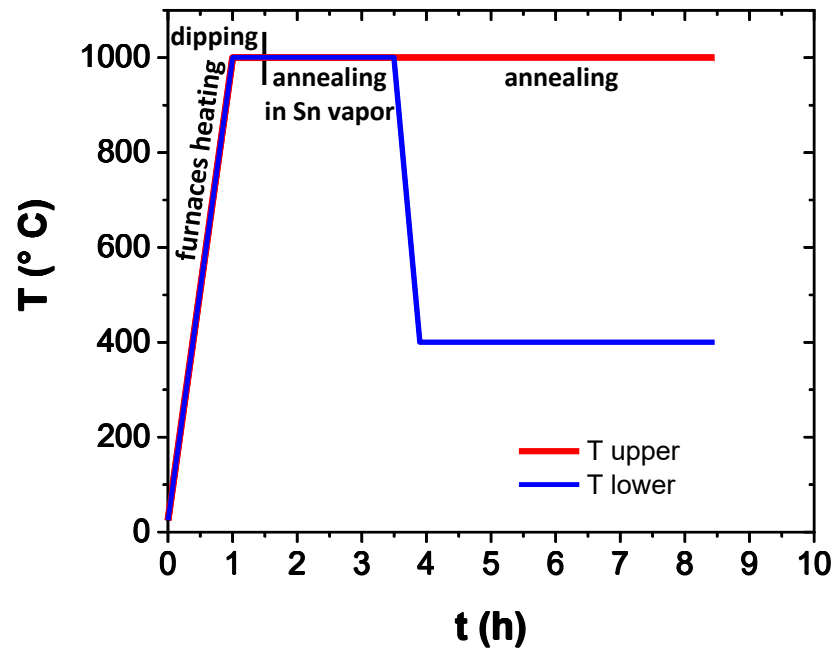


Temperature furnaces profile

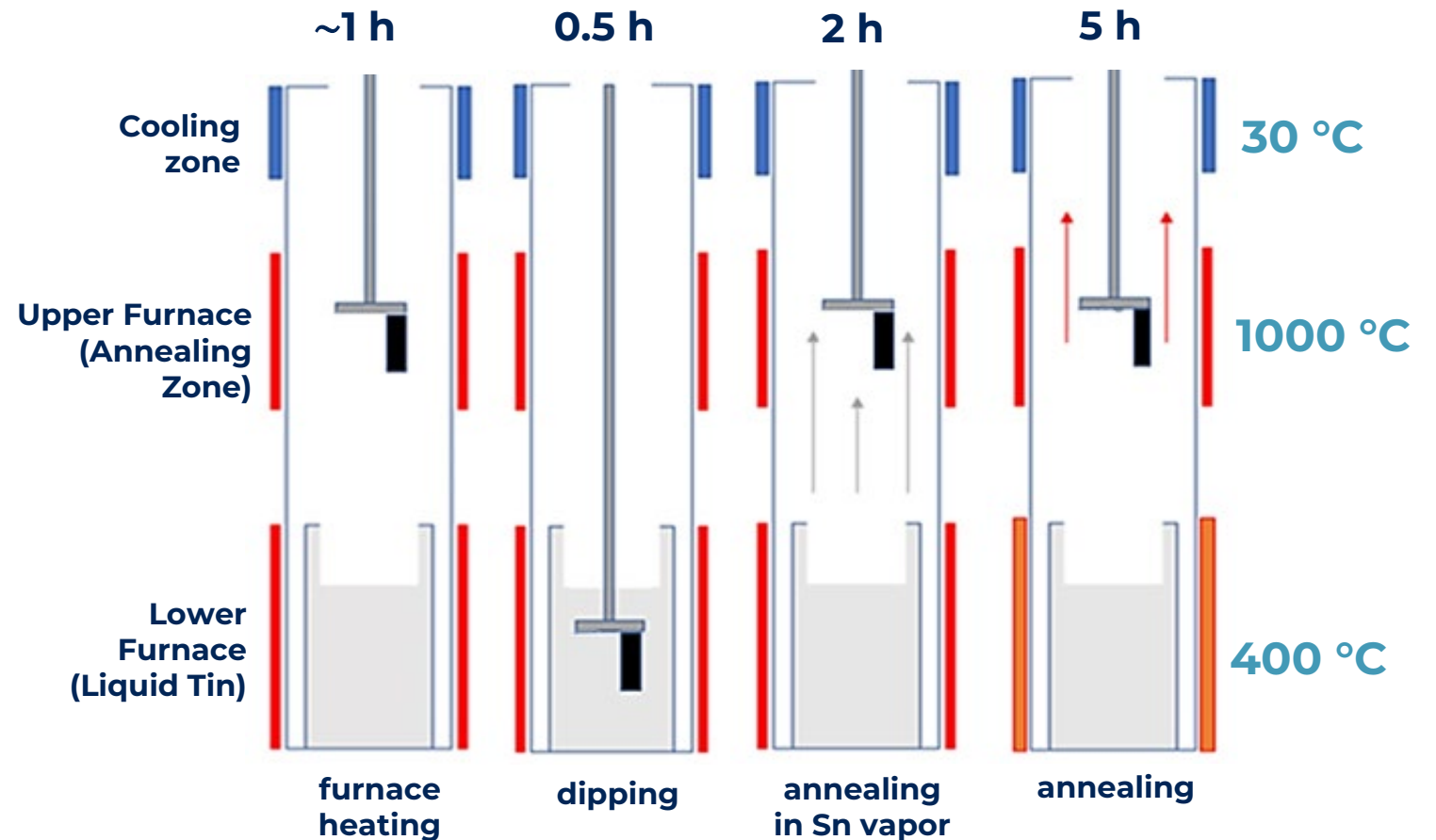


Dipping process (LNL 2006)

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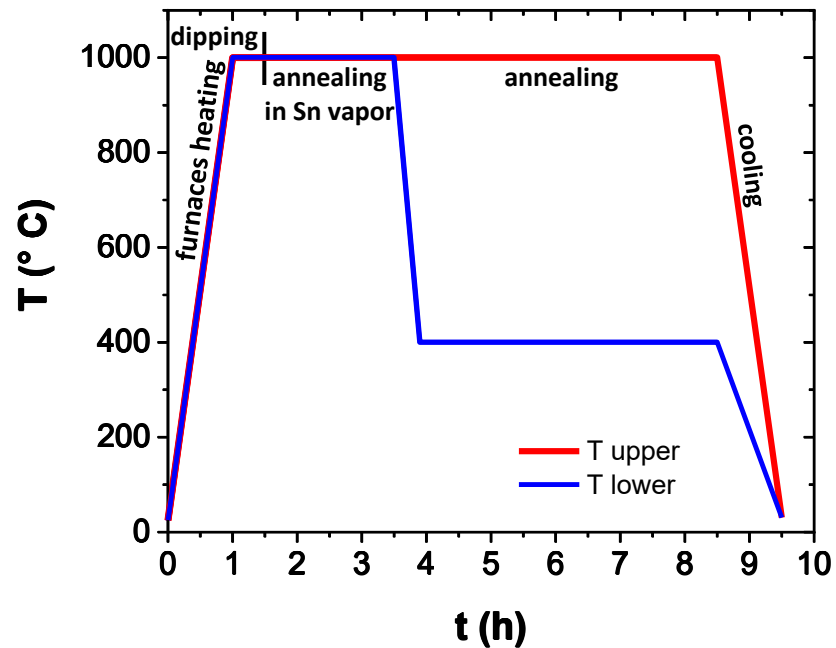


Temperature furnaces profile

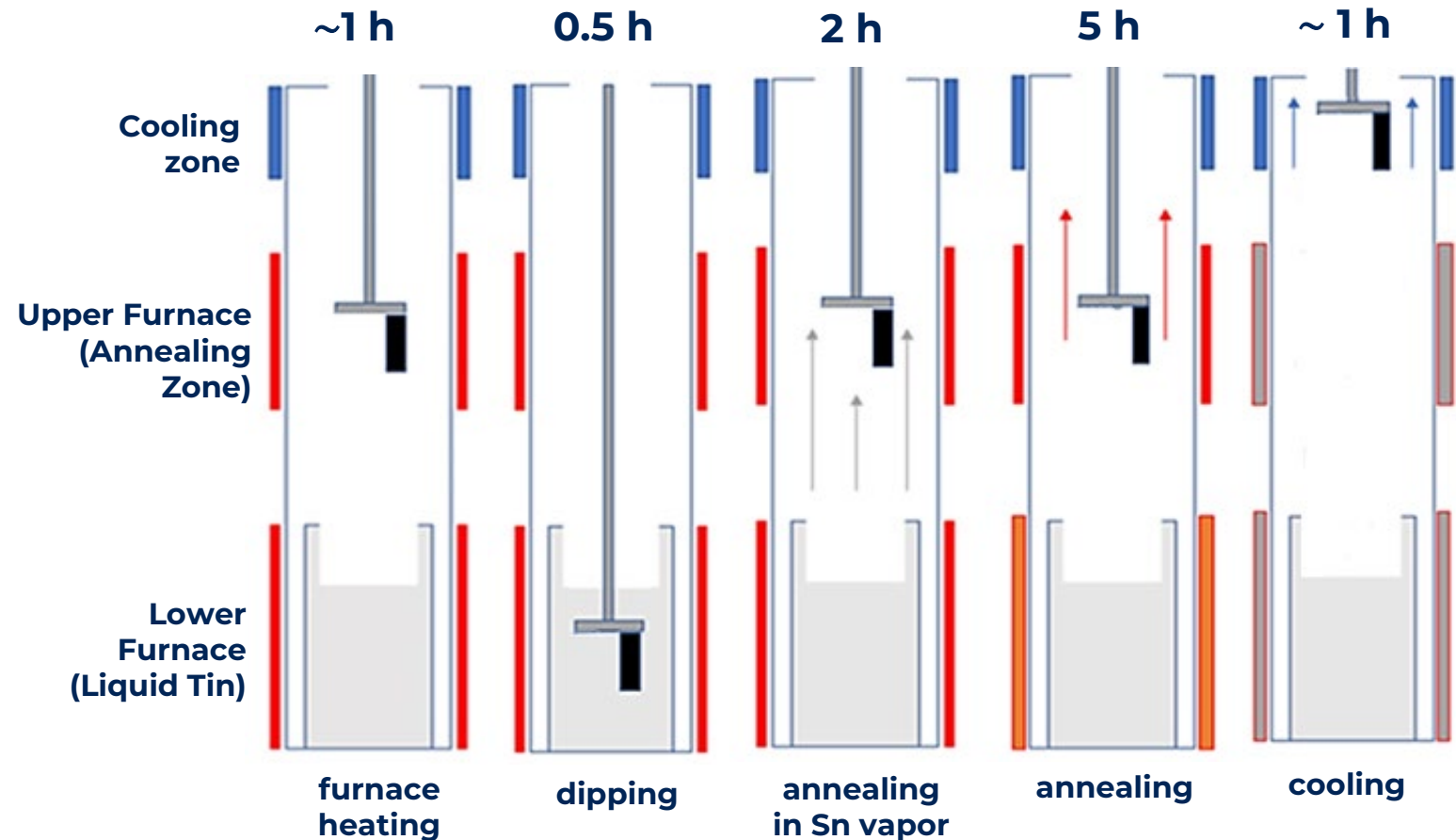


Dipping process (LNL 2006)

S. M. Deambrosis et al., "Al₅ superconductors: An alternative to niobium for RF cavities," Physica C, 2006

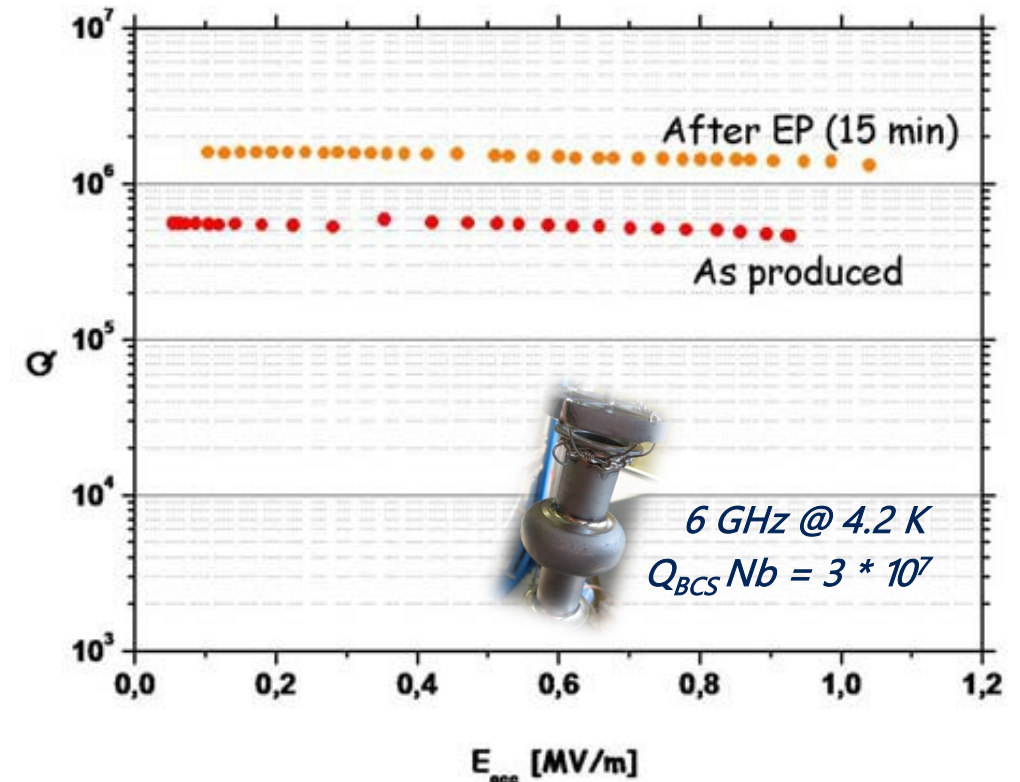
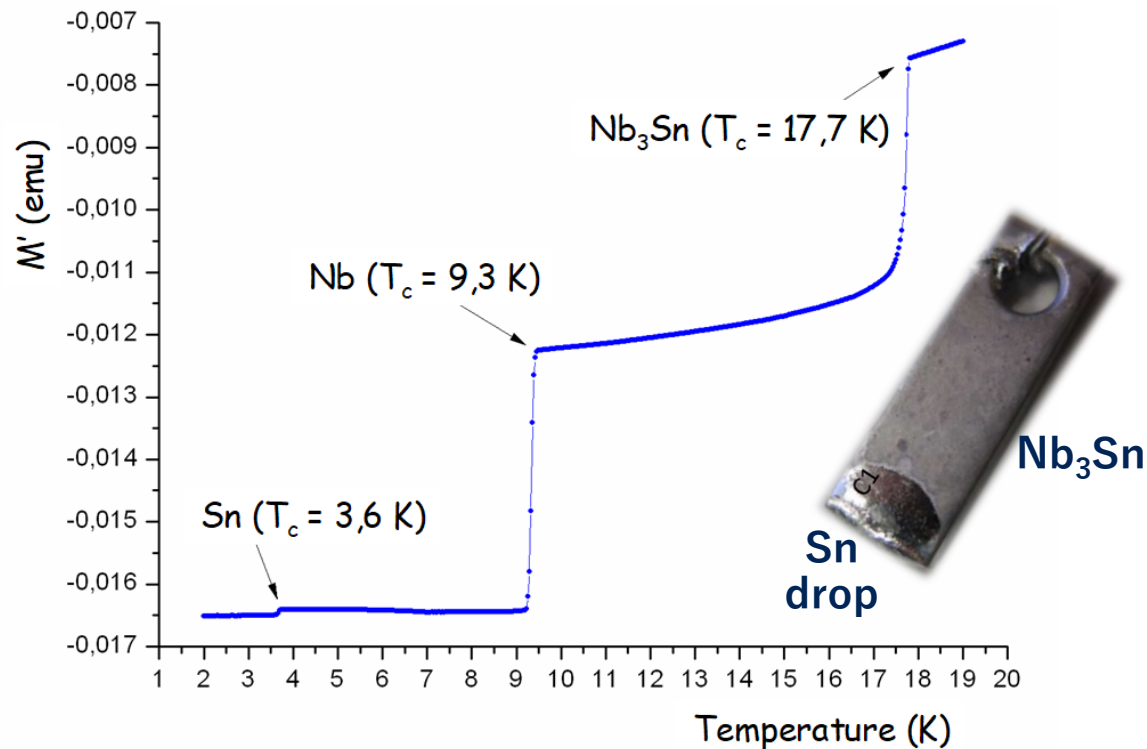


Temperature furnaces profile



Results (LNL 2006)

S. M. Deambrosis et al., "A15 superconductors: An alternative to niobium for RF cavities," *Physica C*, 2006
S. M. Deambrosis, *SRF 2009*



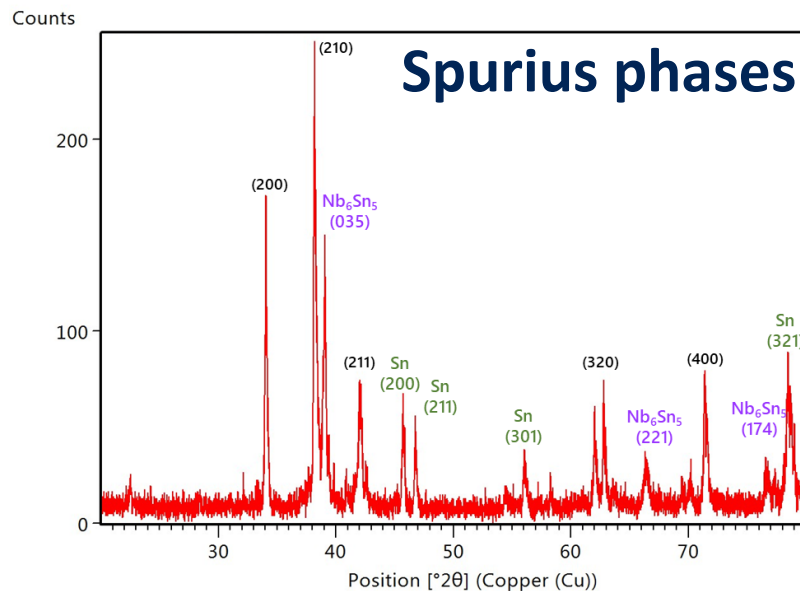
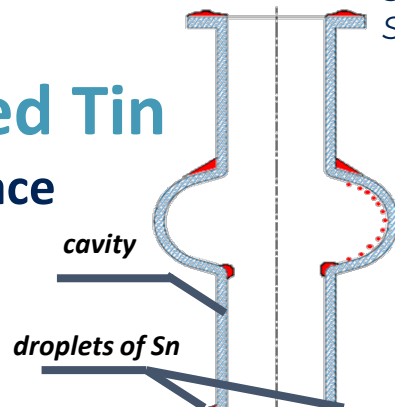
Good performance on **planar samples**

Poor performance on 6 GHz **cavity**

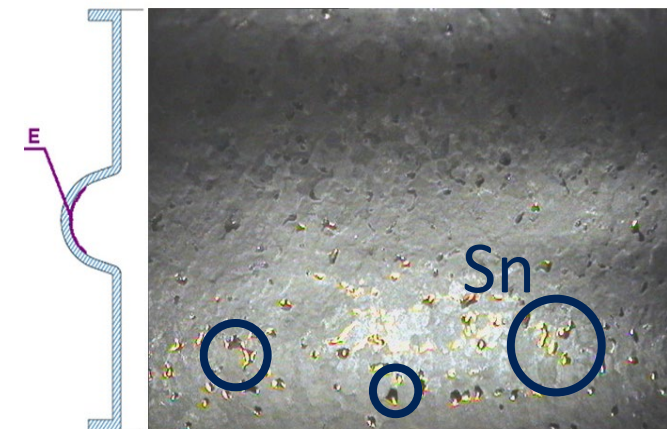
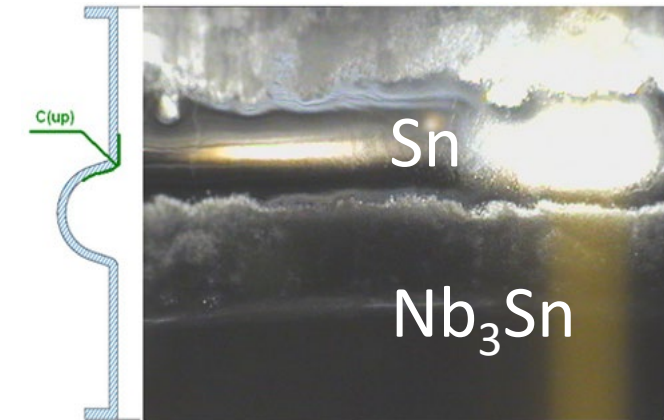
Results (LNL 2006)

S. M. Deambrosis et al., "A15 superconductors: An alternative to niobium for RF cavities," *Physica C*, 2006
S. M. Deambrosis, SRF 2019

Drops of
unreacted Tin
on the surface



External surface

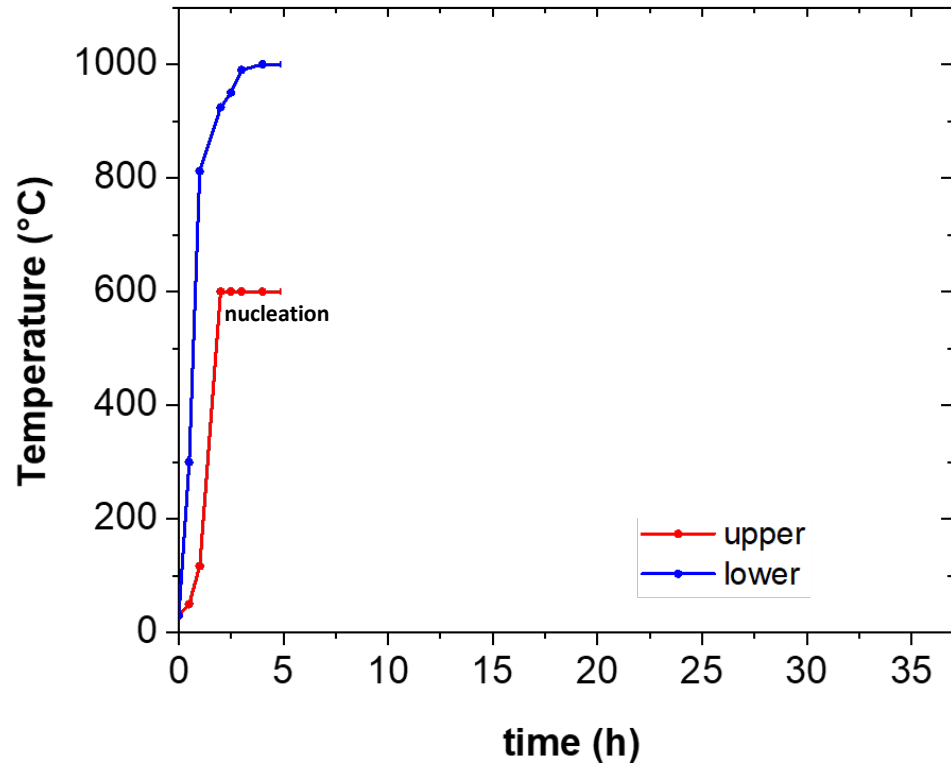


Internal surface

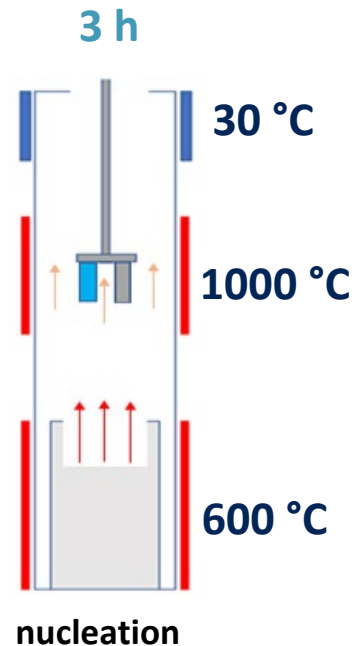
Dipping process optimization and Nb₃Sn target production

Dipping Optimized Process

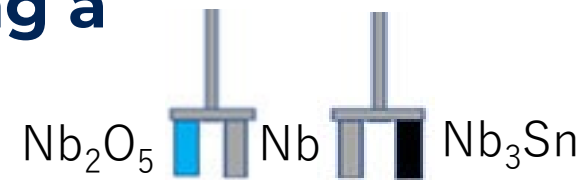
M. Zanierato, SRF 2021



Temperature furnaces profile

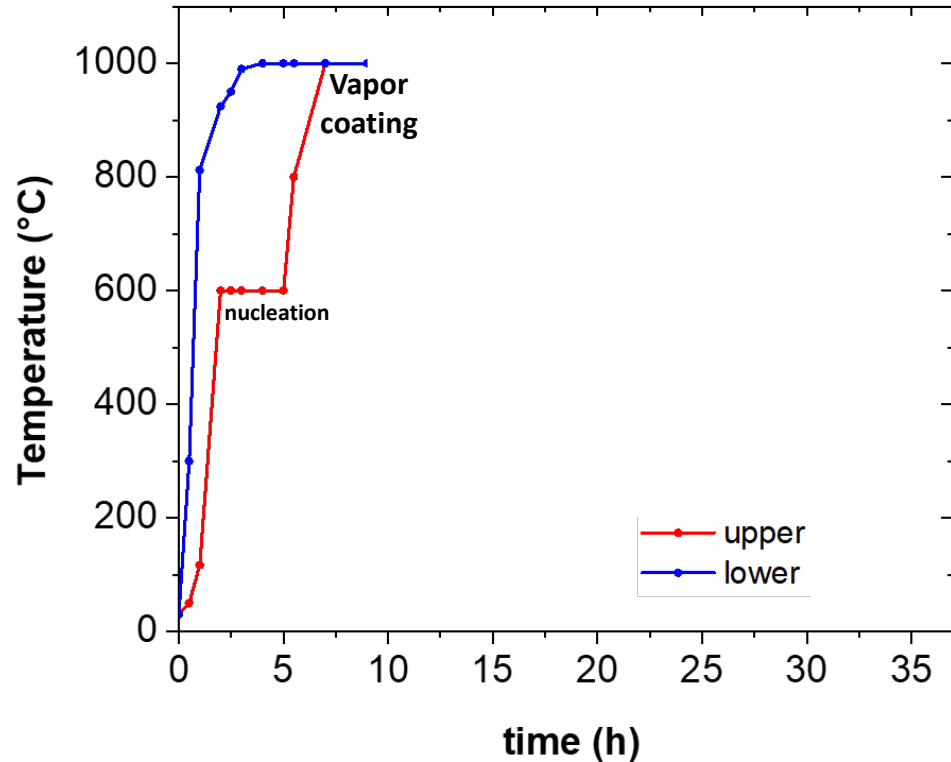


Nucleation improved adding a
vapor coating step
on anodized Nb samples

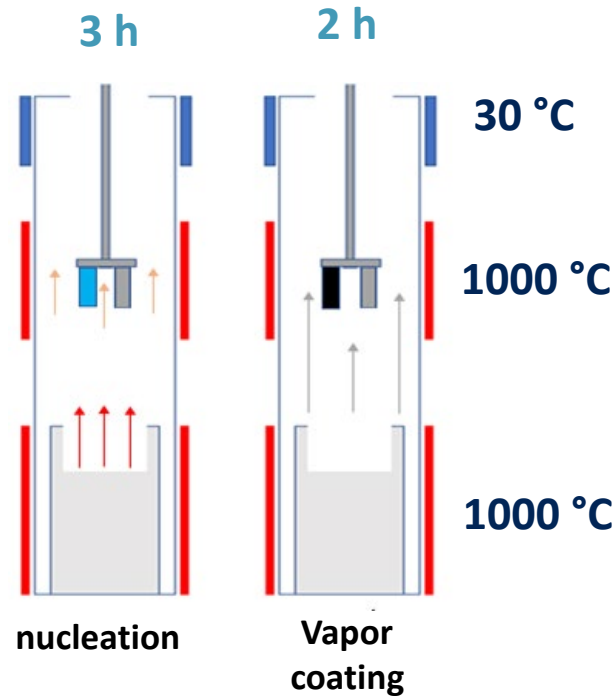


Dipping Optimized Process

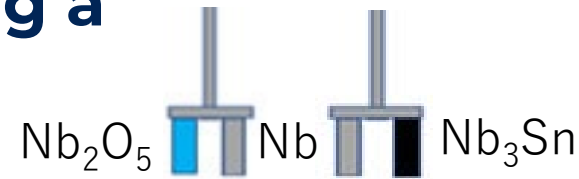
M. Zanierato, SRF 2021



Temperature furnaces profile

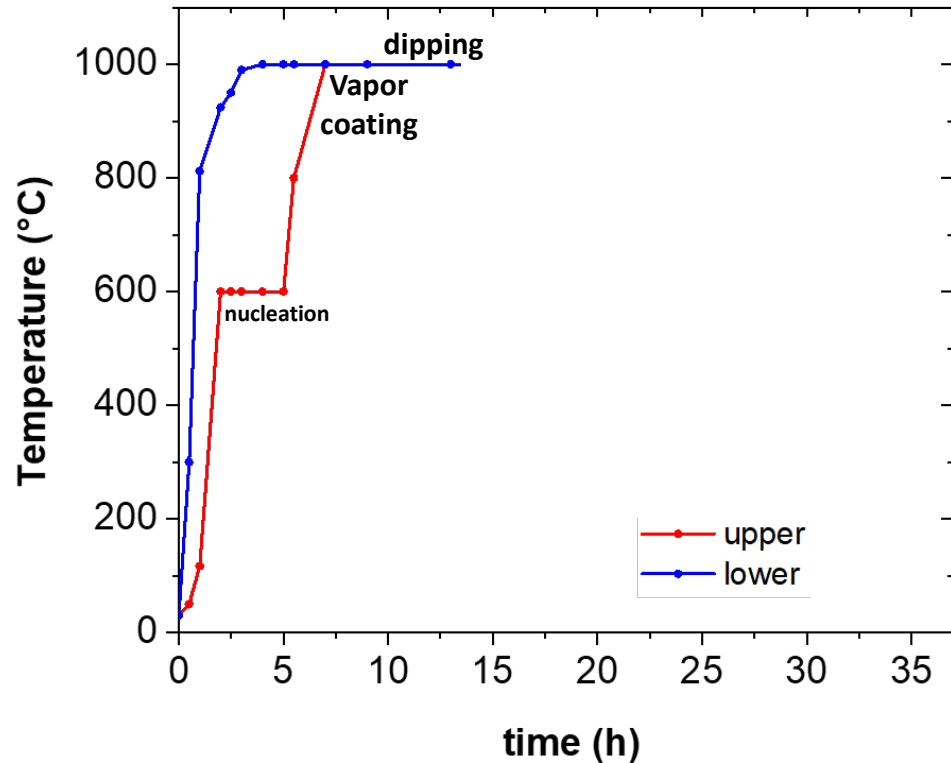


Nucleation improved adding a
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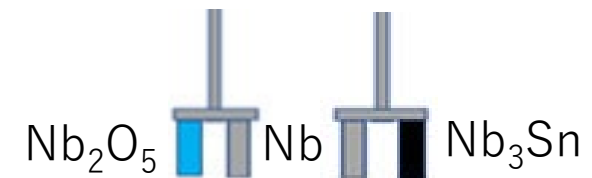
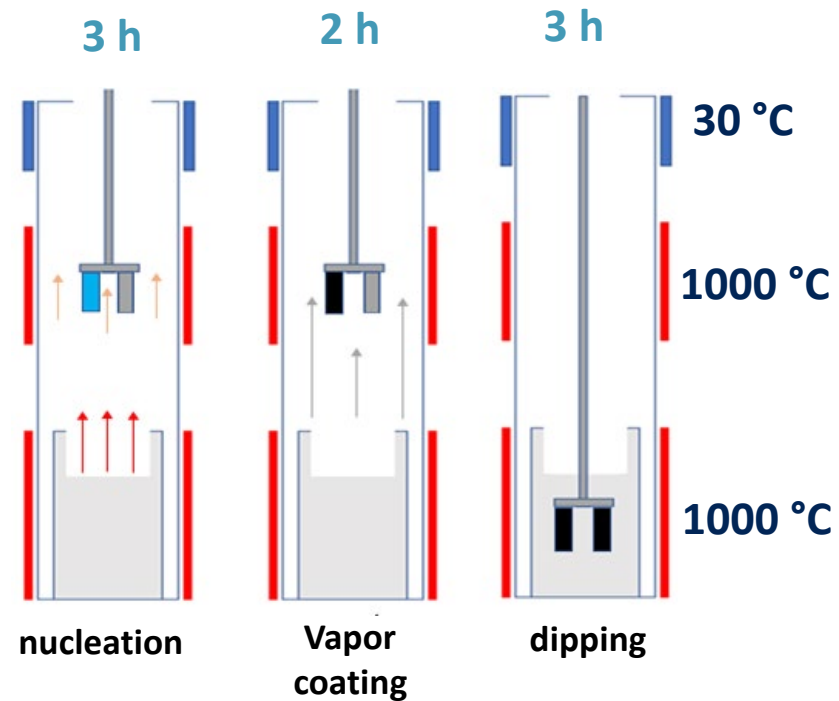


Dipping Optimized Process

M. Zanierato, SRF 2021

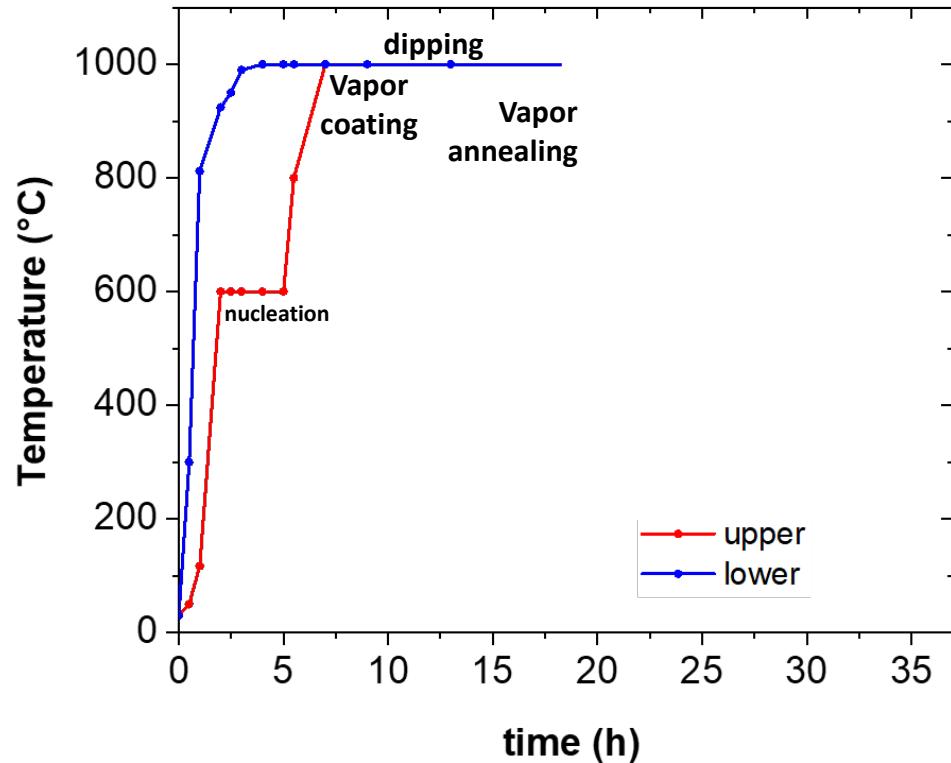


Temperature furnaces profile

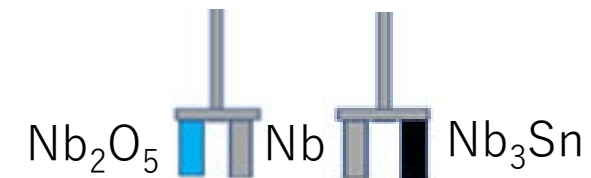
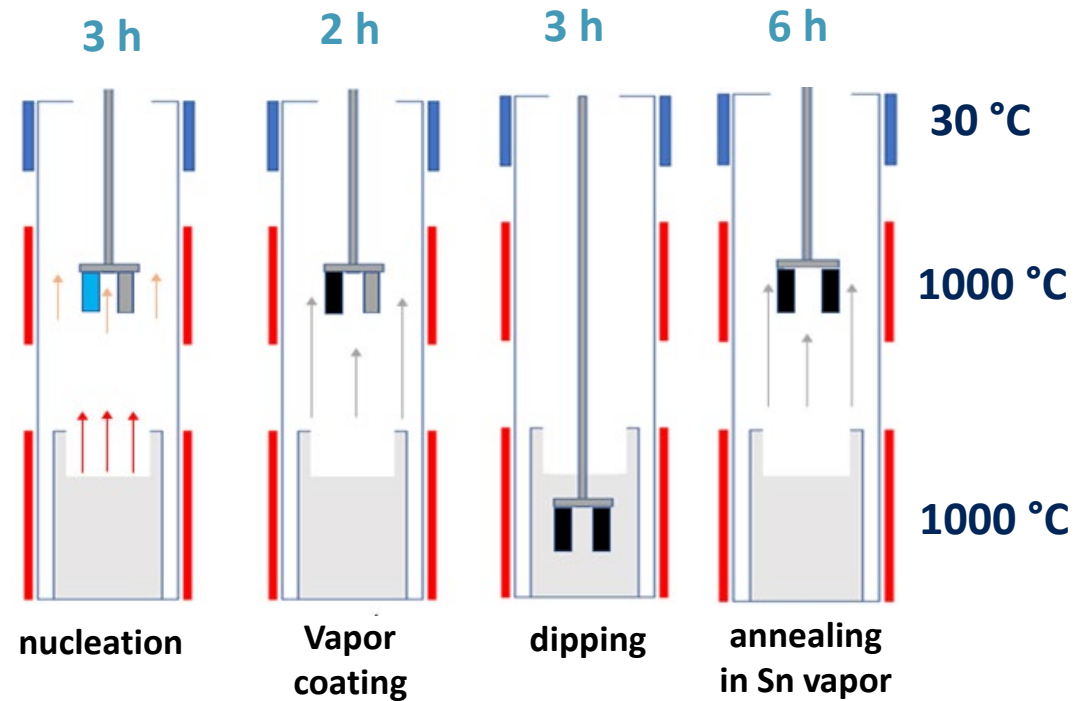


Dipping Optimized Process

M. Zanierato, SRF 2021

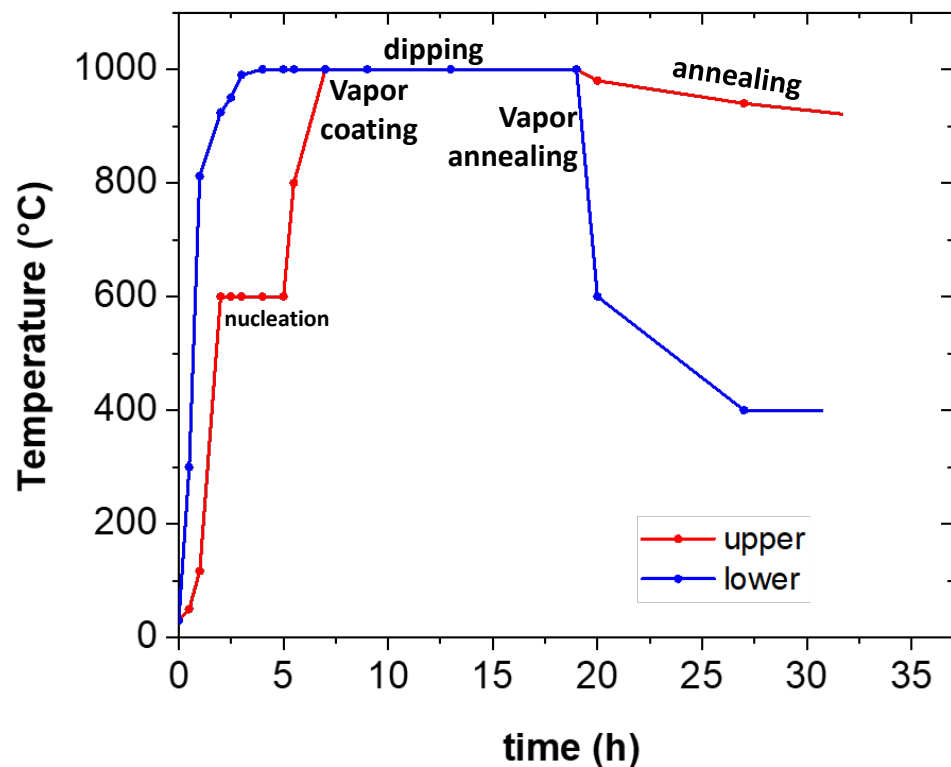


Temperature furnaces profile

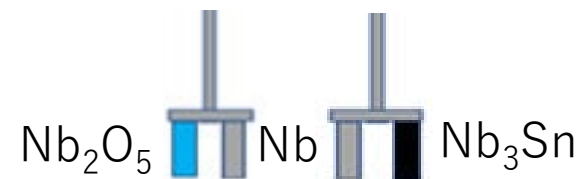
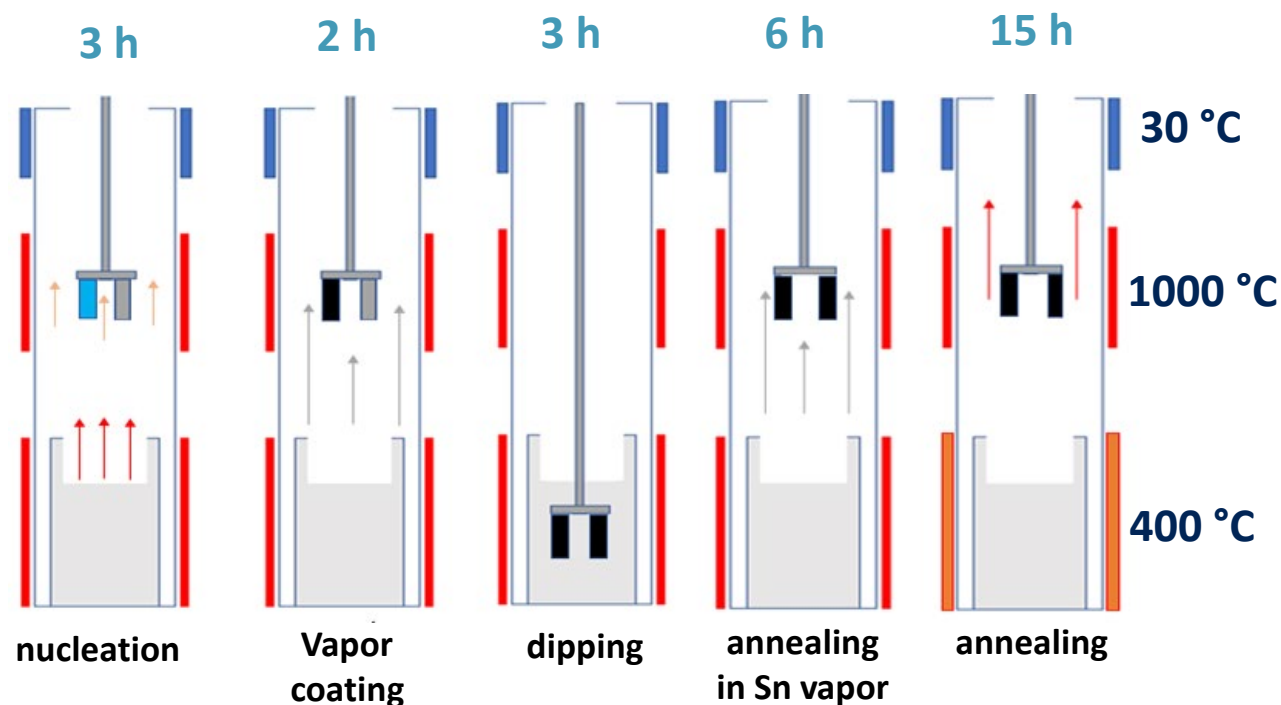


Dipping Optimized Process

M. Zanierato, SRF 2021

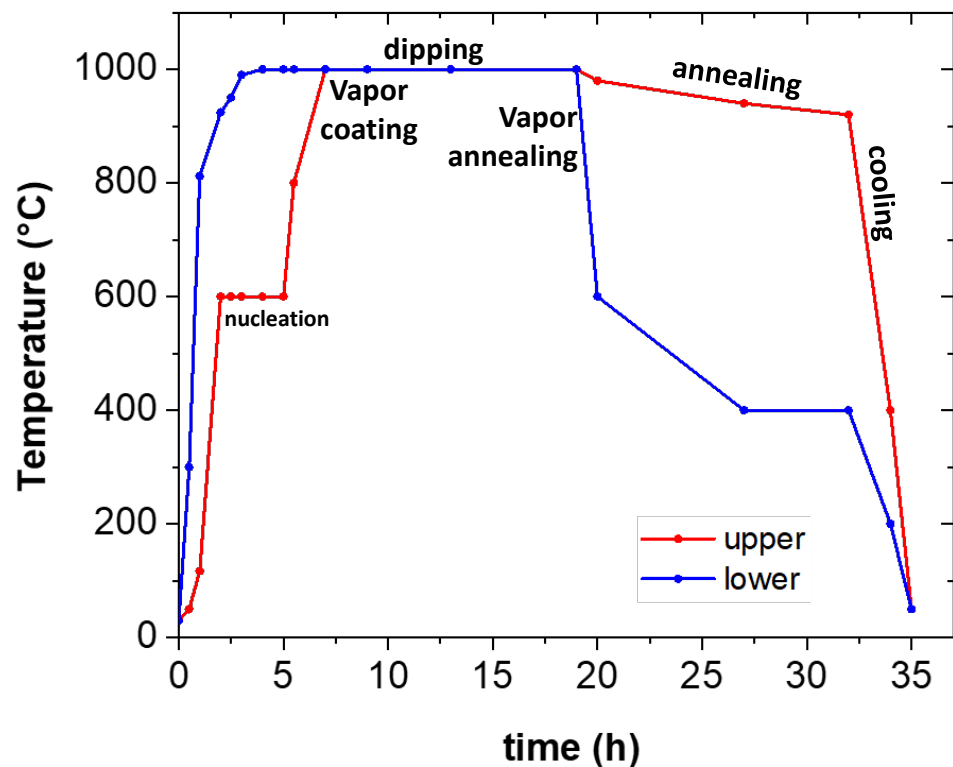


Temperature furnaces profile

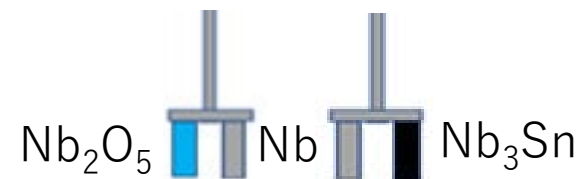
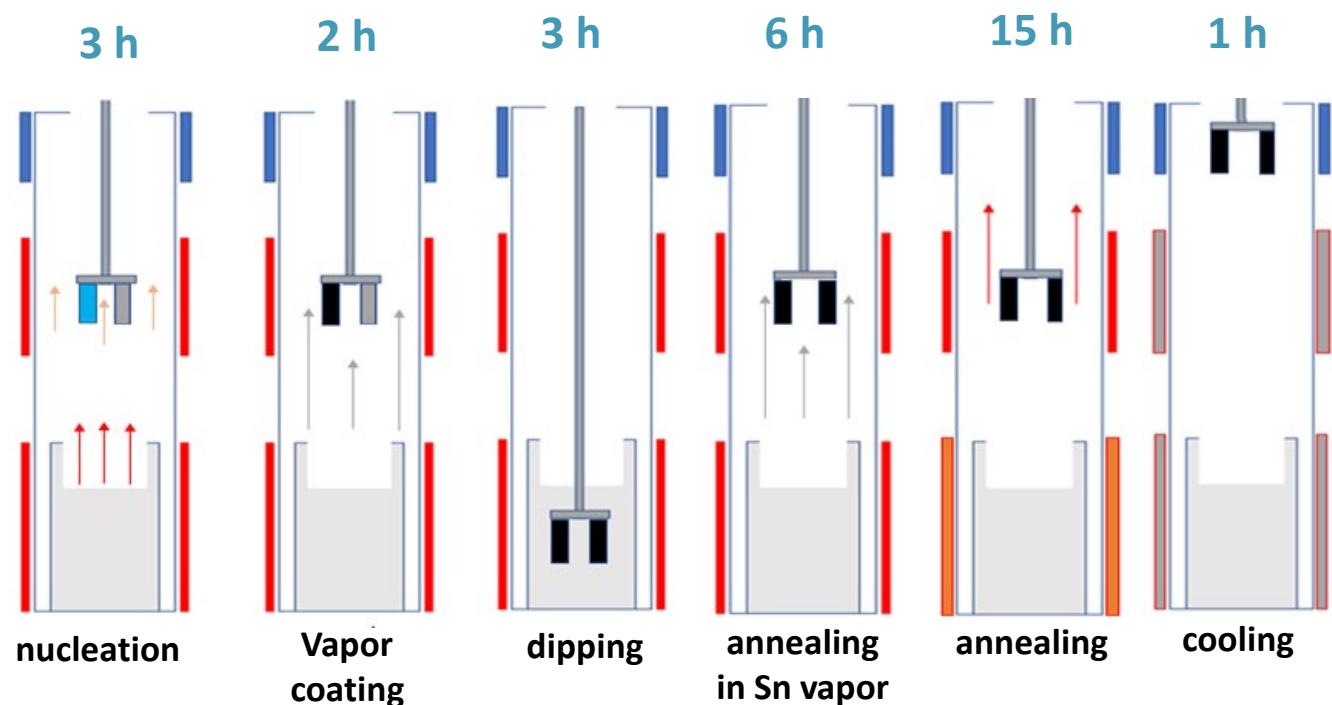


Dipping Optimized Process

M. Zanierato, SRF 2021



Temperature furnaces profile

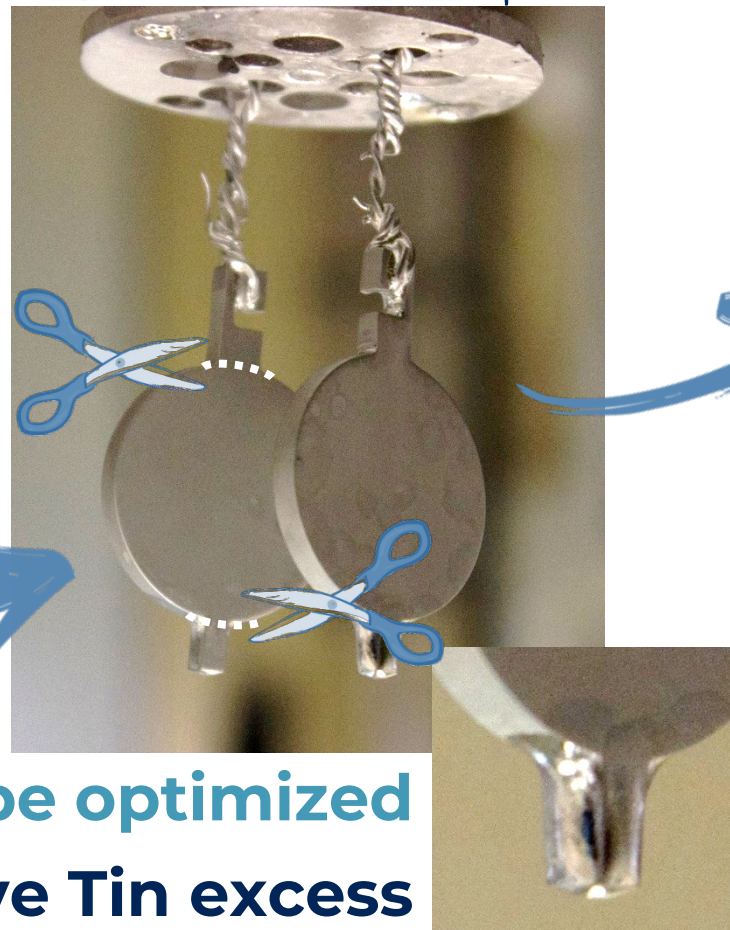


Test with 1" target

Anodized samples

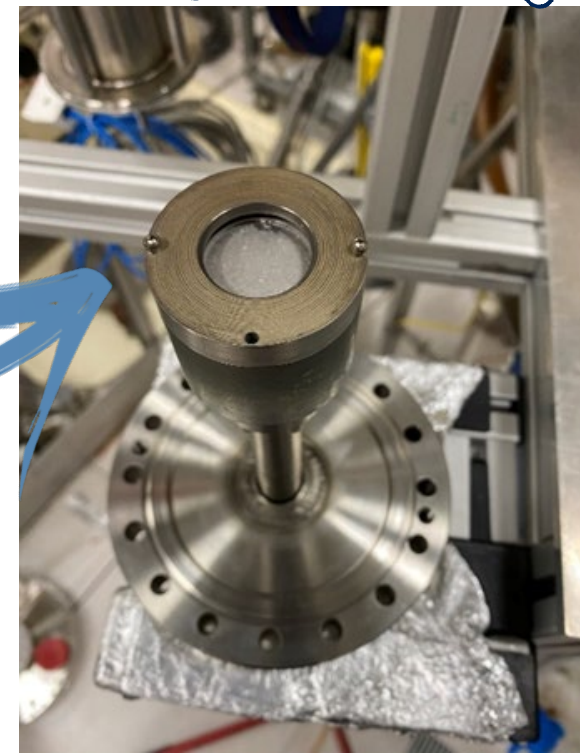


Nb_3Sn coated samples



**Shape optimized
to collect and remove Tin excess**

1" Magnetron ready



Dipping time - thickness

C. Pira, Thin Films Workshop SRF 2021
M. Zanierato, SRF 2021

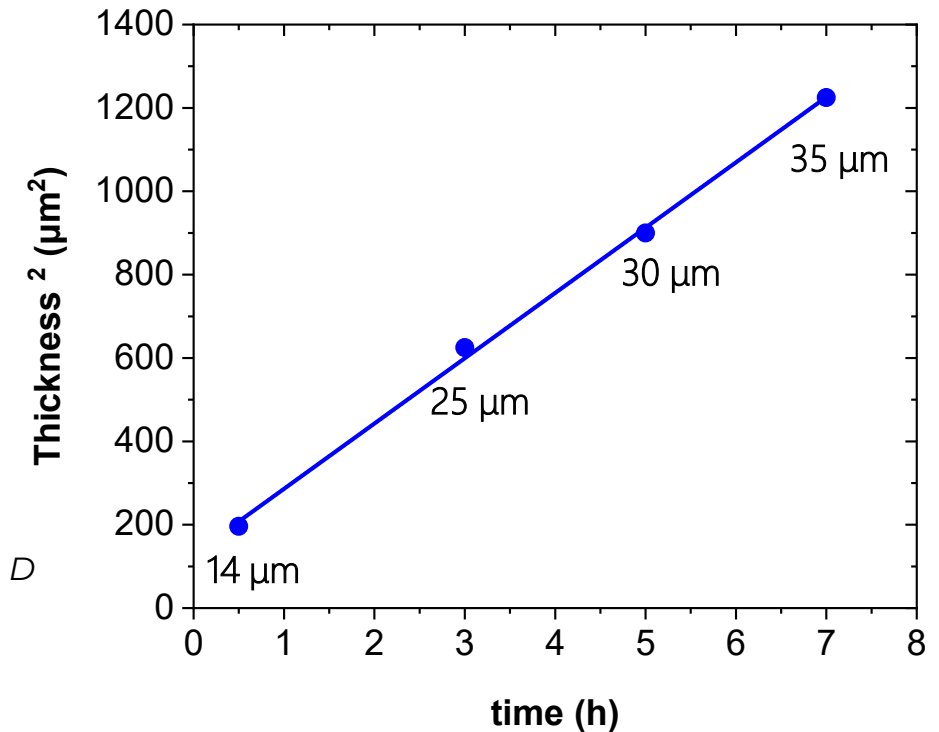
Nb₃Sn growing rate by dipping is related to the Sn diffusion in Nb and can be described by Fick' laws of diffusion

$$x^2 = kt$$

x: Nb₃Sn thickness

t: dipping time

k: a costant that takes in account the diffusion coefficient D



$$x^2(\mu\text{m}^2) = 157 \cdot t(\text{h}) + 130$$

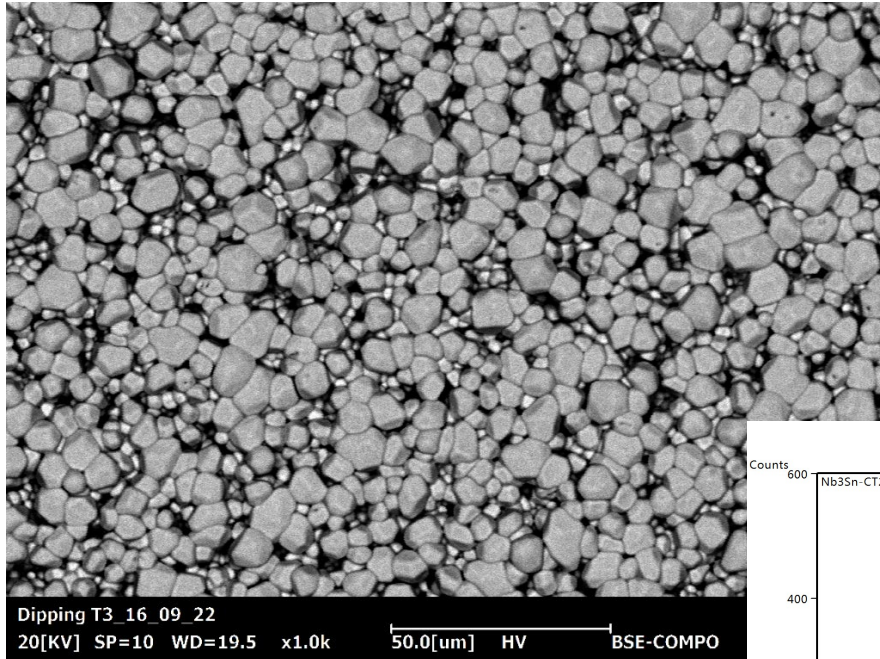
$$R^2 = 0.9983$$

100 μm → ~ 63 hours of dipping!

24 hours of dipping → ~ 62 μm

in progress

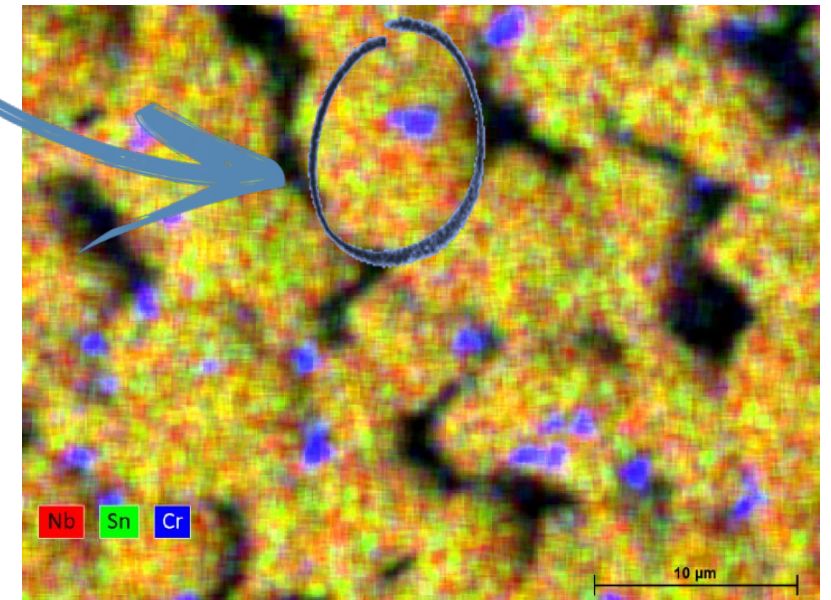
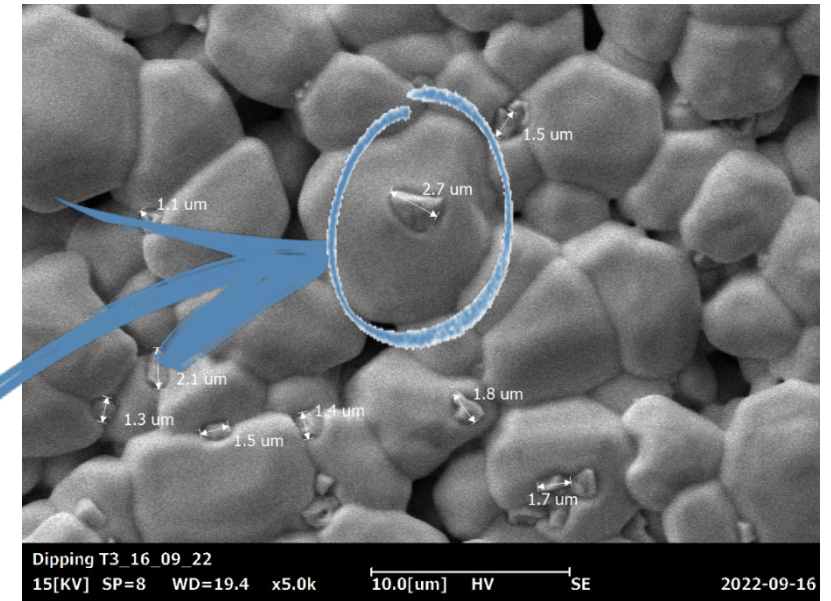
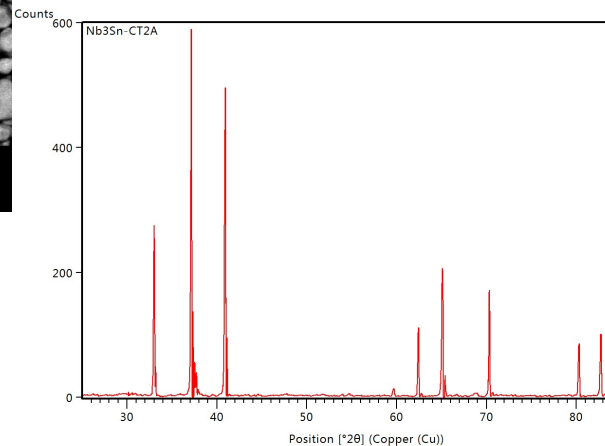
Target Morphology (SEM + EDS characterization)



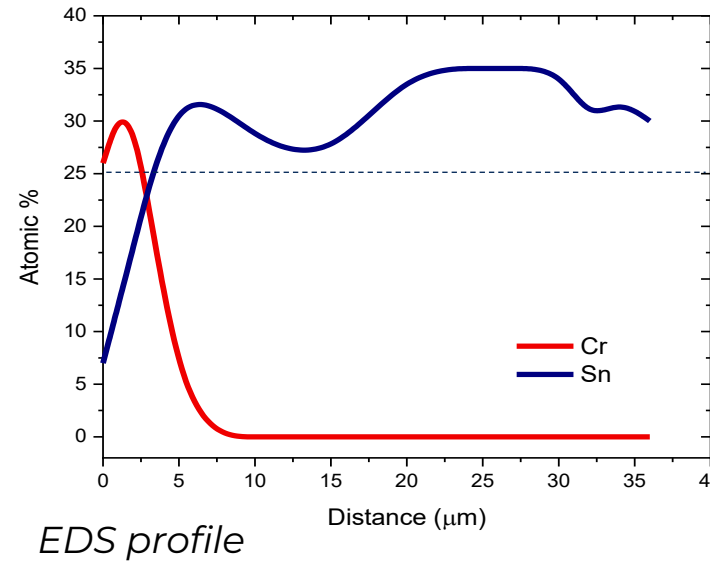
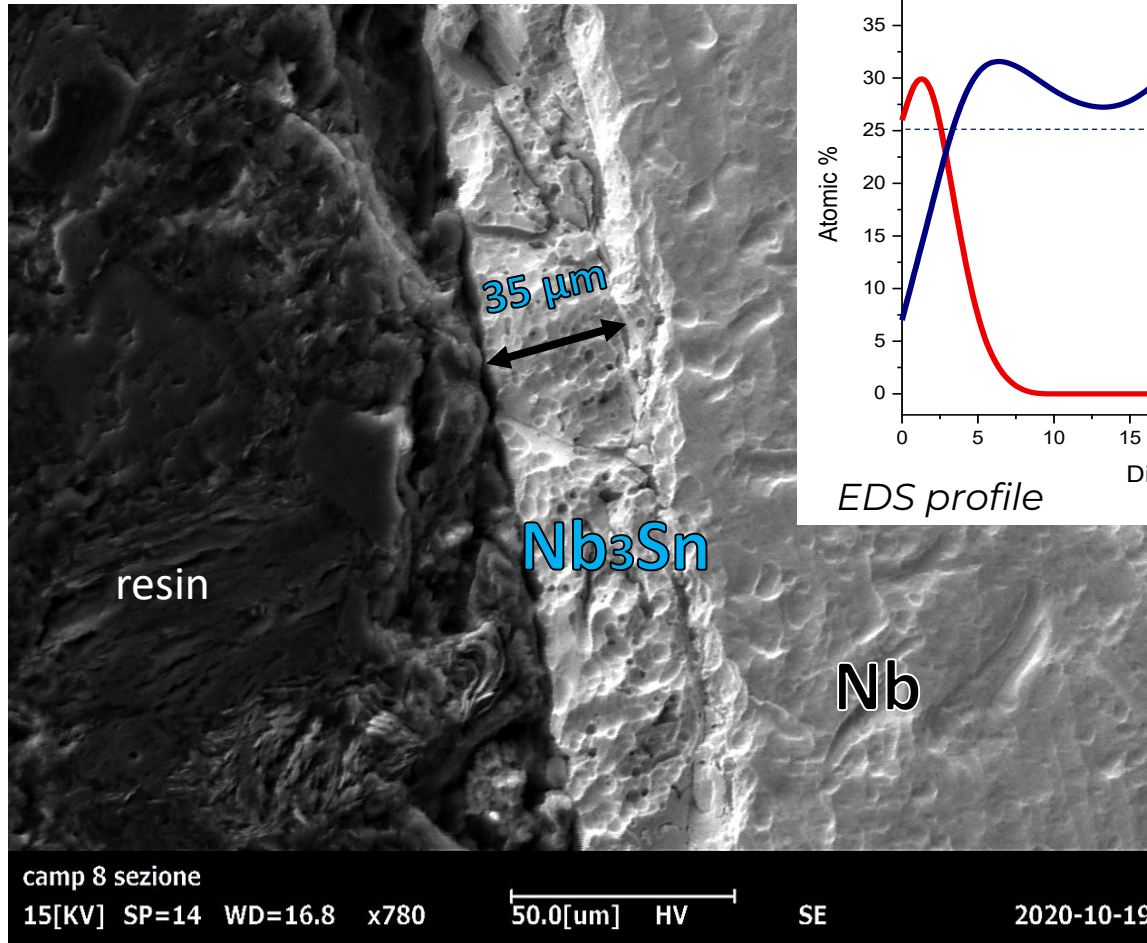
**Stoichiometric
Nb-Sn composition**

XRD shows only Nb₃Sn phase

**Chromium
contamination**
(10-20% on surface)
Ni and Fe are also present



Target cross section



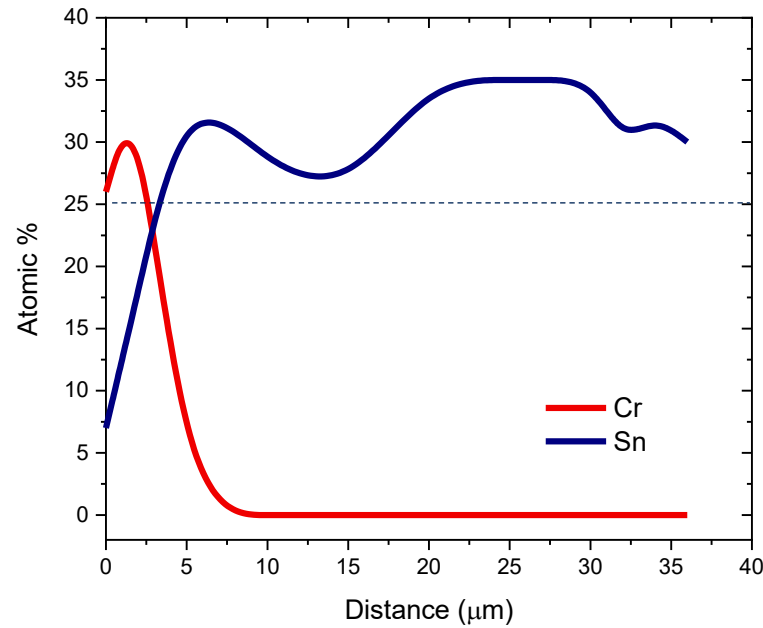
Contamination is **superficial**

No contamination in **Sn** crucible

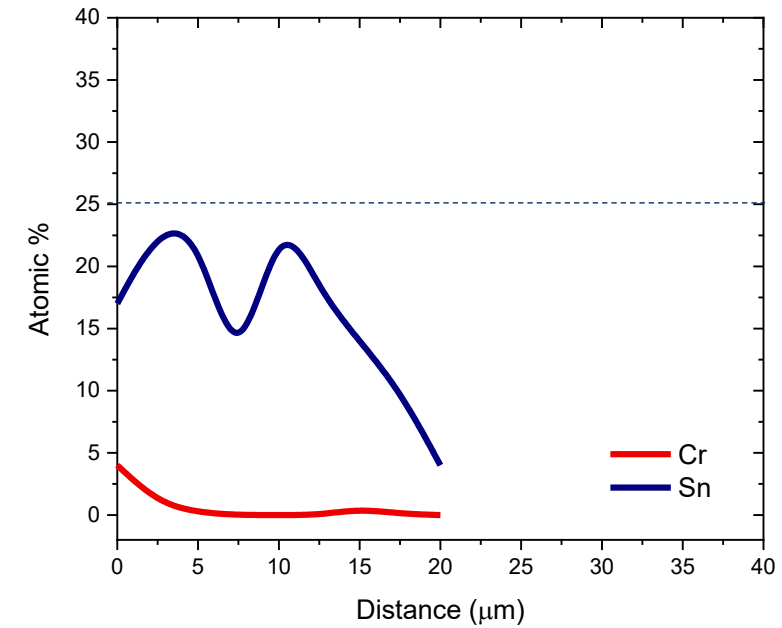
Main candidate for **Cr** contamination:
Vacuum chamber made by **Inconel Alloy**

Tin content modulation

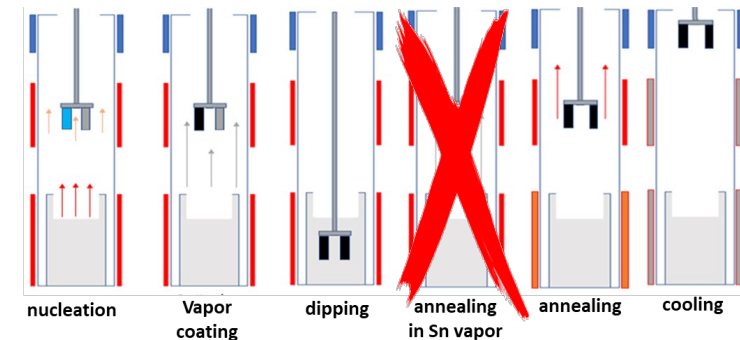
With Vapor Annealing Step



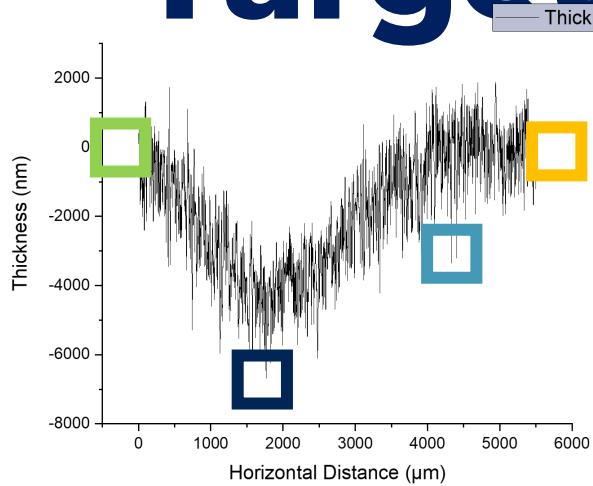
Without Vapor Annealing Step



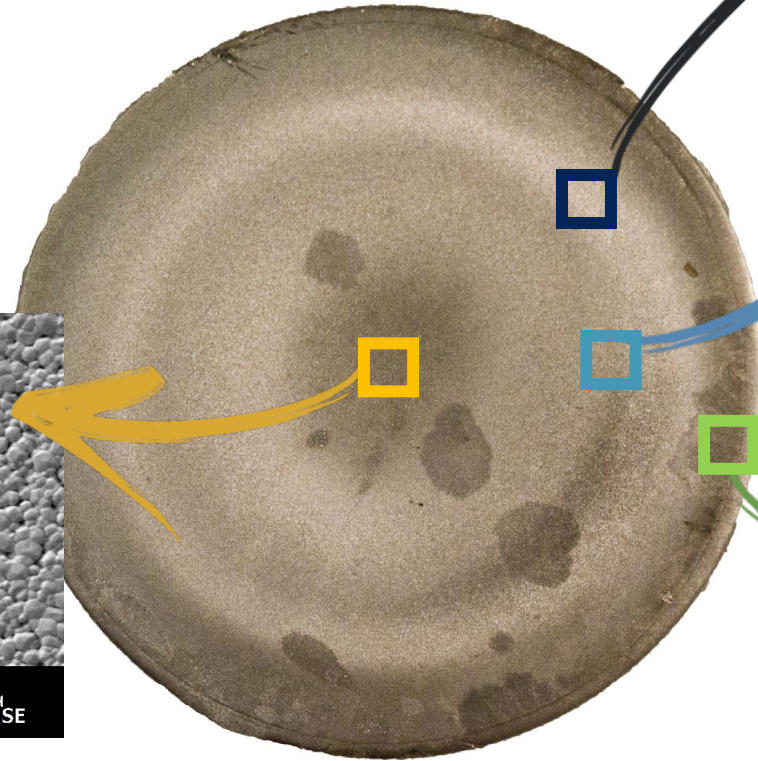
**Vapor annealing step
can be used to modulate
Tin content**



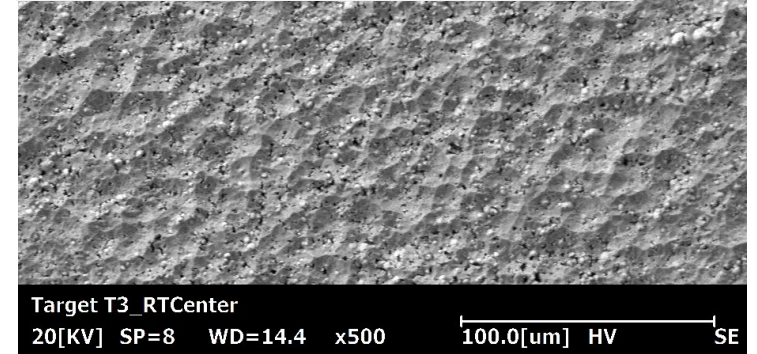
Target surface



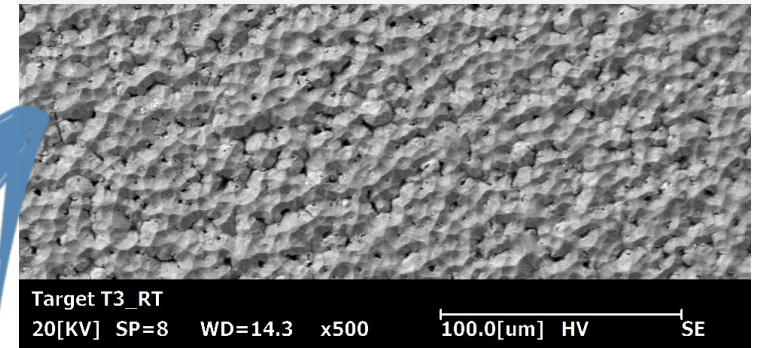
~6 microns eroded
700 nm coated



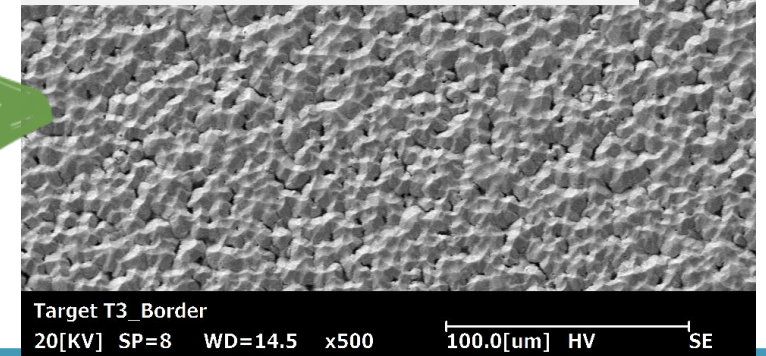
Race Track: **Sn 22.8%**



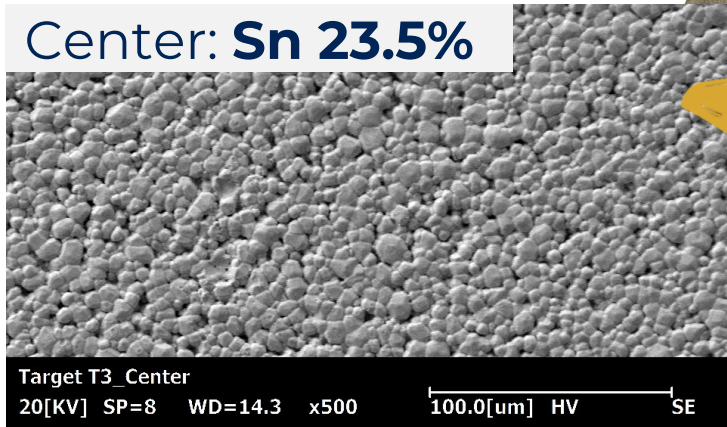
Race Track side: **Sn 23.2%**



Ext. border: **Sn 23.0%**



Center: **Sn 23.5%**



First sputtering test on Quartz

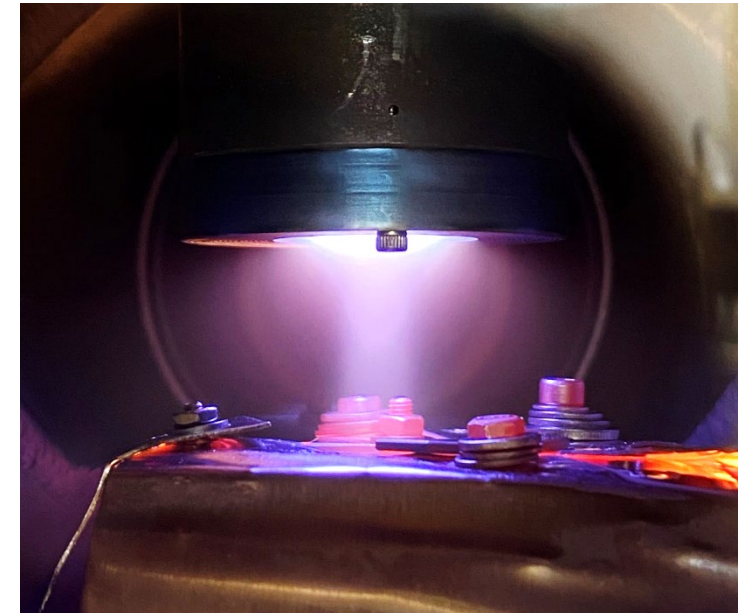
- **1" target** prepared by **Dipping** (30 microns thick)

- Coating on **quartz** samples by MS

$I = 0.1 \text{ A}$ (5 mA/cm^2)

$t = 30 \text{ min}$

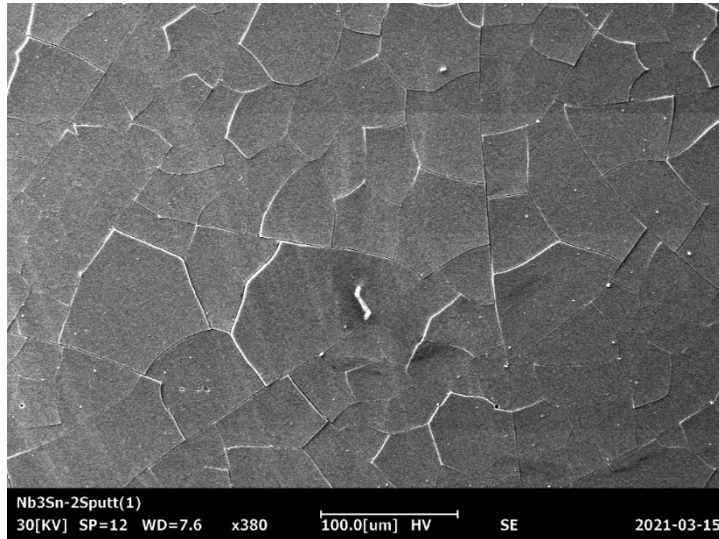
$T = 750 \text{ }^\circ\text{C}$



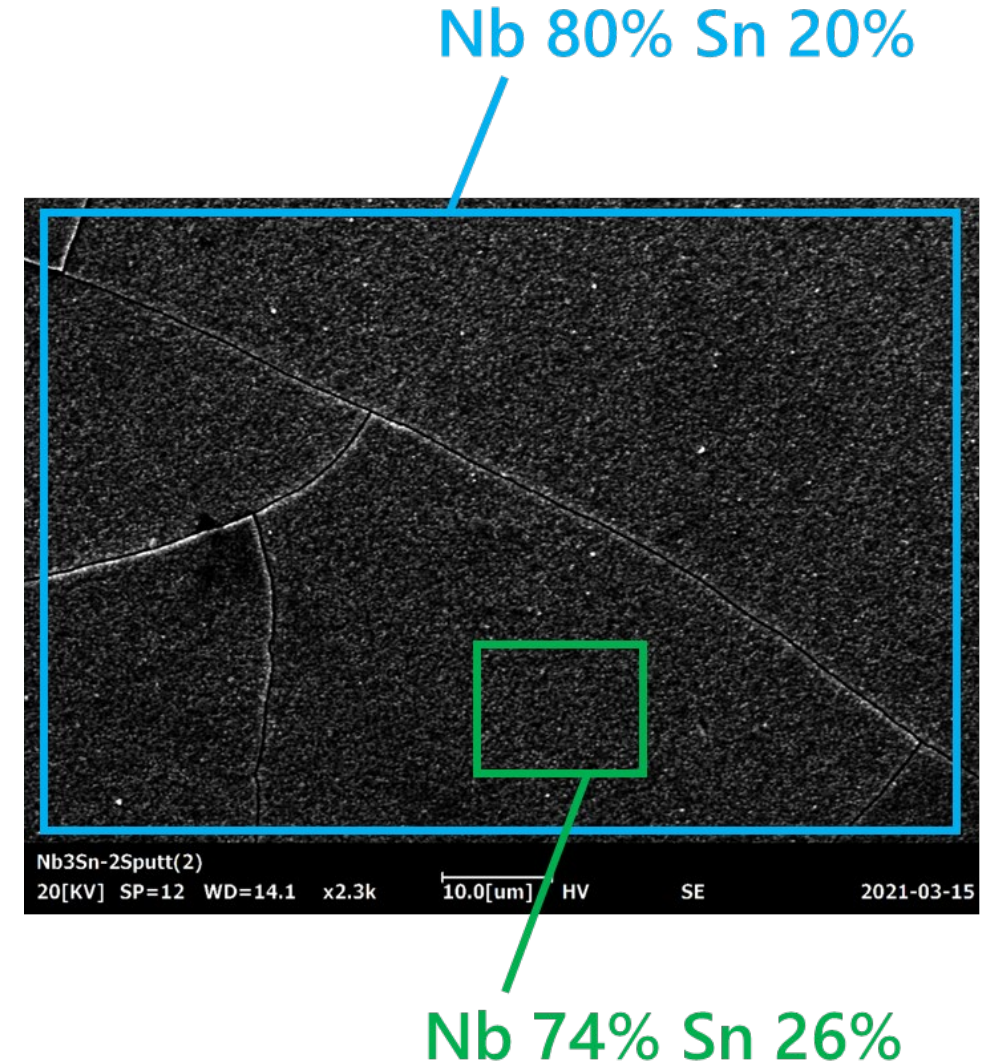
Zanierato et al,
SRF Proceedings 2021

- Process stopped when V started to decrease

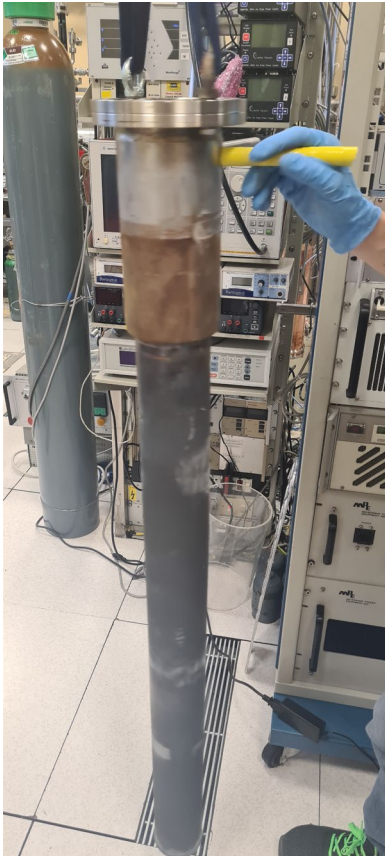
First sputtering test on Quartz



- **Good composition**
- **No Cr** visible by EDS
- **Cracks** due to Quartz substrate
- **No Tc** measured
- **2 New targets** ready for new tests

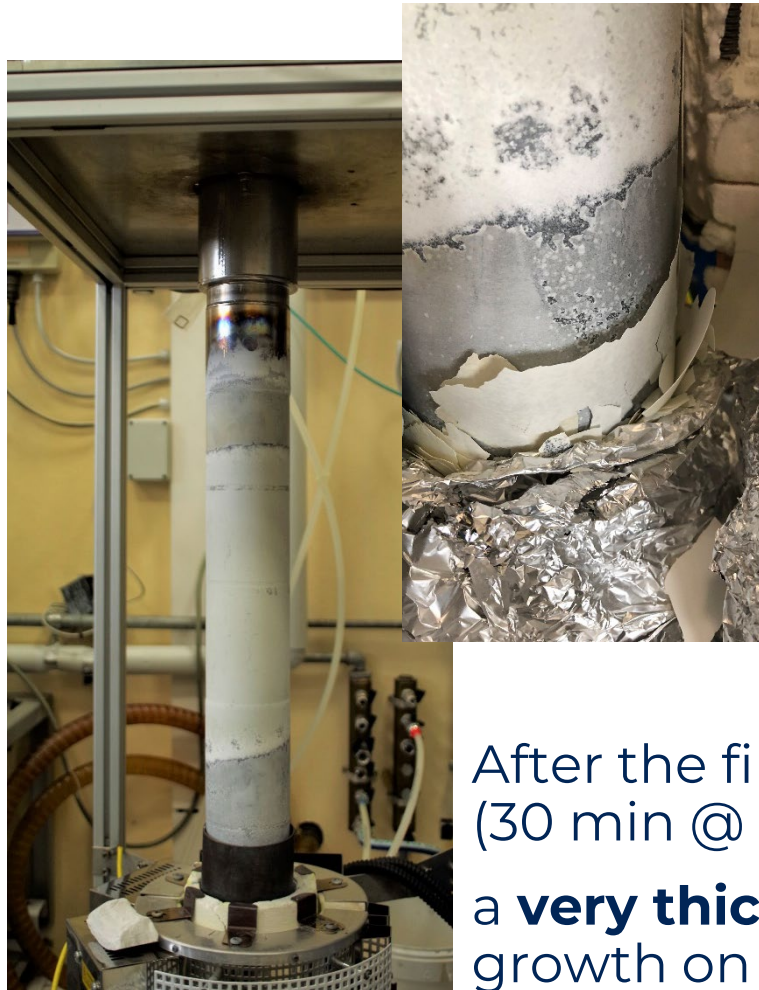


Solution to Cr contamination



Inconel chamber
replaced by a
Nb chamber
produced at Zanon

New problems have come...



After the first test
(30 min @ 1000 °C)
a **very thick film of Nb₂O₅**
growth on the external surface

Nb is not stable as Inconel at high T in air

We tested several solutions without success:

- *Nb anodization*
- *High T paints*
- *Allumina by HVOF*



*We are redesigning the
system with inductive heating
and a double chamber to avoid
oxidation of Nb chamber*

Conclusions

- Proved the possibility of realizing targets via LTD
- Easy modulation of target thickness and Tin content

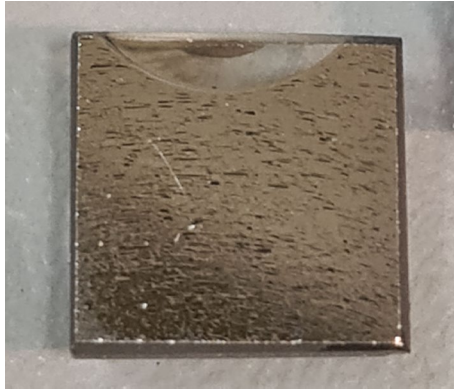
Two main aspect to optimize:

➔ **Chromium poisoning**

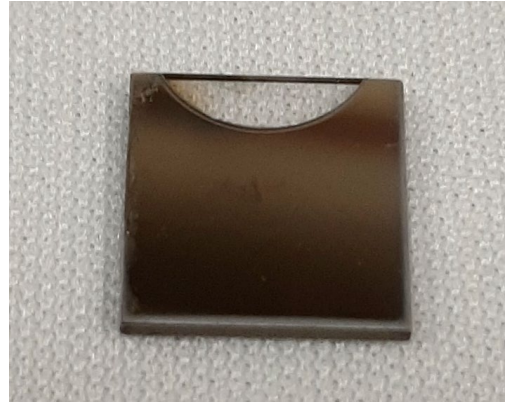
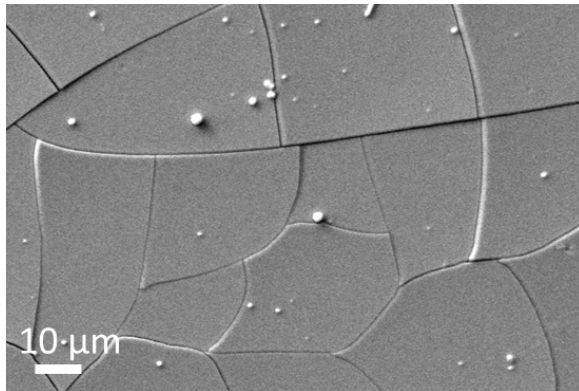
➔ **Study the magnetron sputtering deposition parameters**

in progress with commercial sintered Nb₃Sn targets

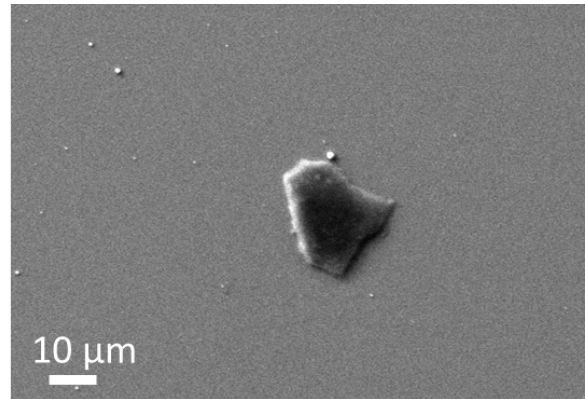
Take home message



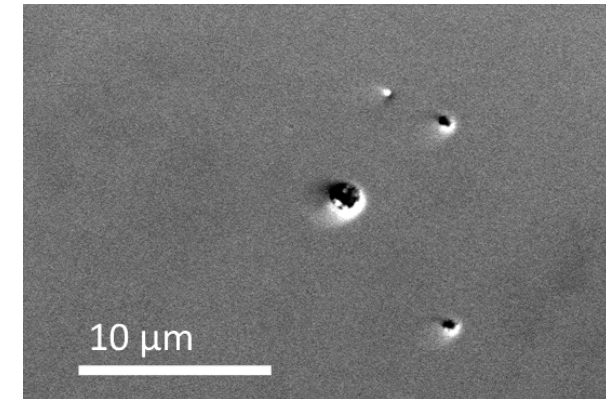
Quartz



Sapphire



Copper



Do not use quartz for temperatures above 550 C!

Thanks to the LNL INFN team:

Alessandro Salmaso, Davide Ford, Luca Torrassa, Eduard Chyhyrynets, Fabrizio Stivanello, Giorgio Keppel, Oscar Azzolini



Special thanks to **Vanessa Garcia Diaz**



Open postdoc position @LNL:
(deadline October 30th)

<https://l.infn.it/job>

cristian.pira@lnl.infn.it



Thanks for your attention

cristian.pira@lnl.infn.it

Work supported by the INFN CSN5



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Research and Innovation programme under GA No 101004730.



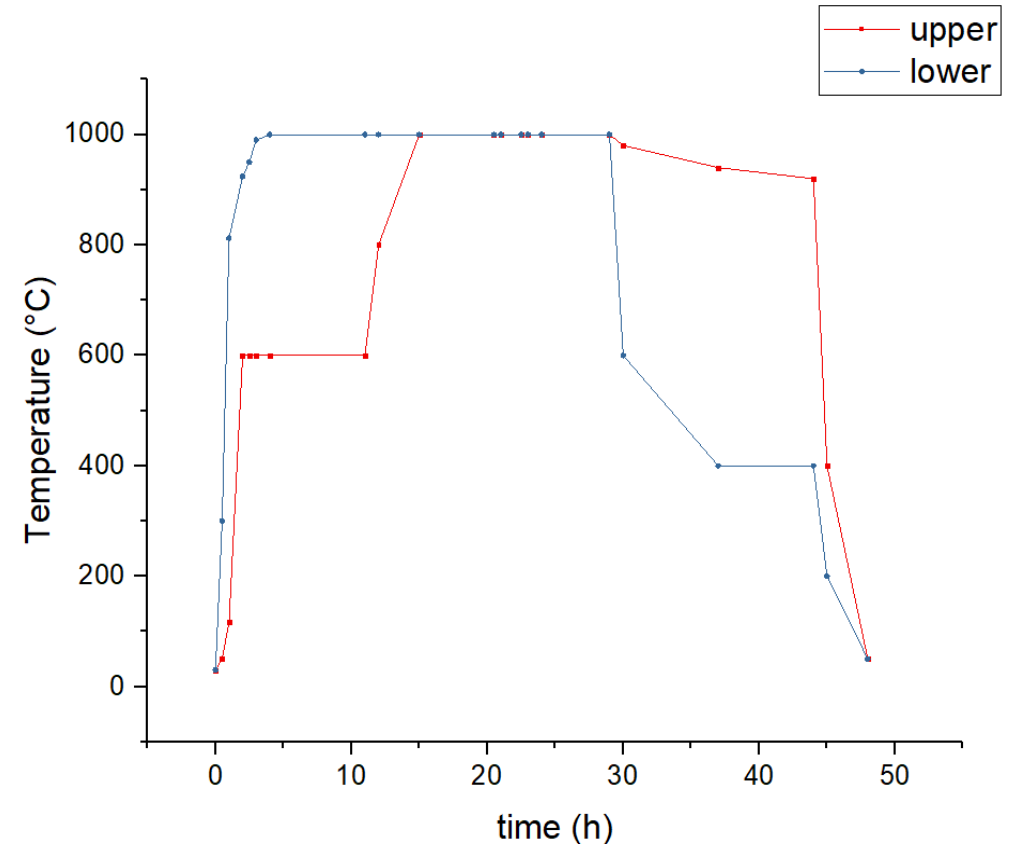
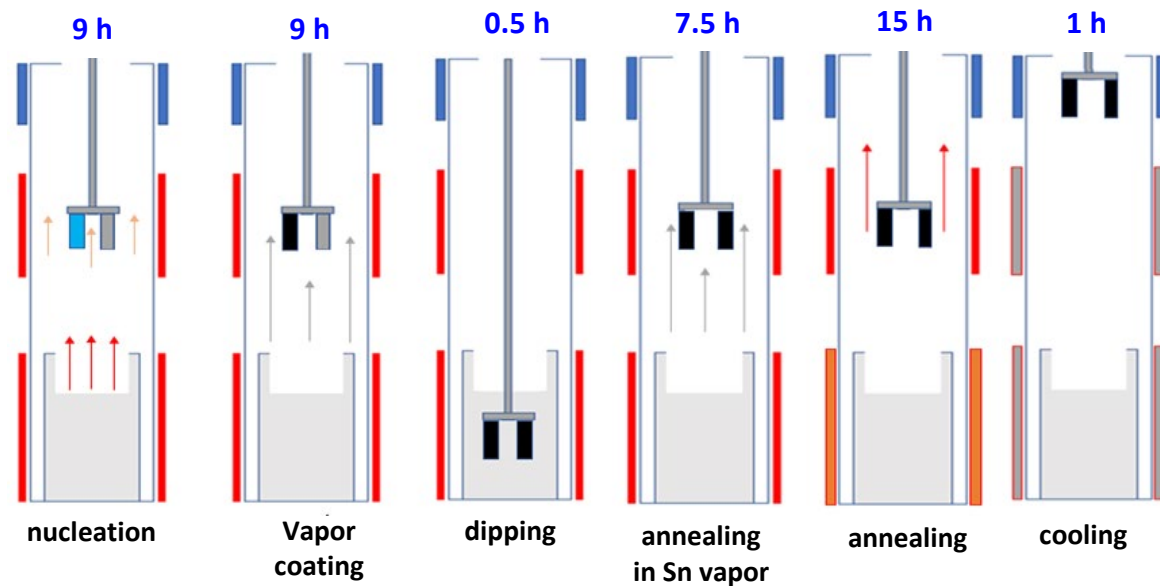
Backup slides

How does the new process work in RF?

How does the new process work in RF?

Process has been adapted to reduce Nb₃Sn thickness

(5-10 microns as the old cavities)



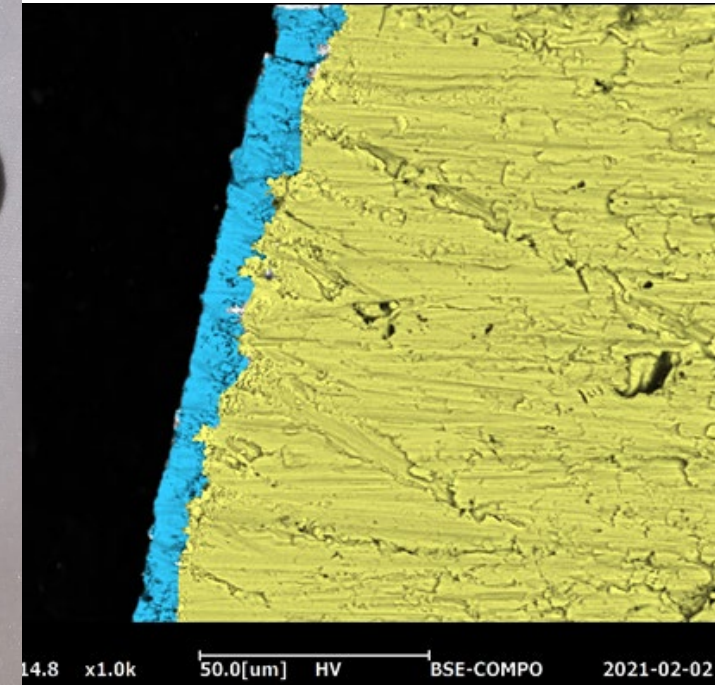
6 GHz cavity #1 (only geometry test)

First test in a broken cavity to
test possible geometry effect

No tin drops!

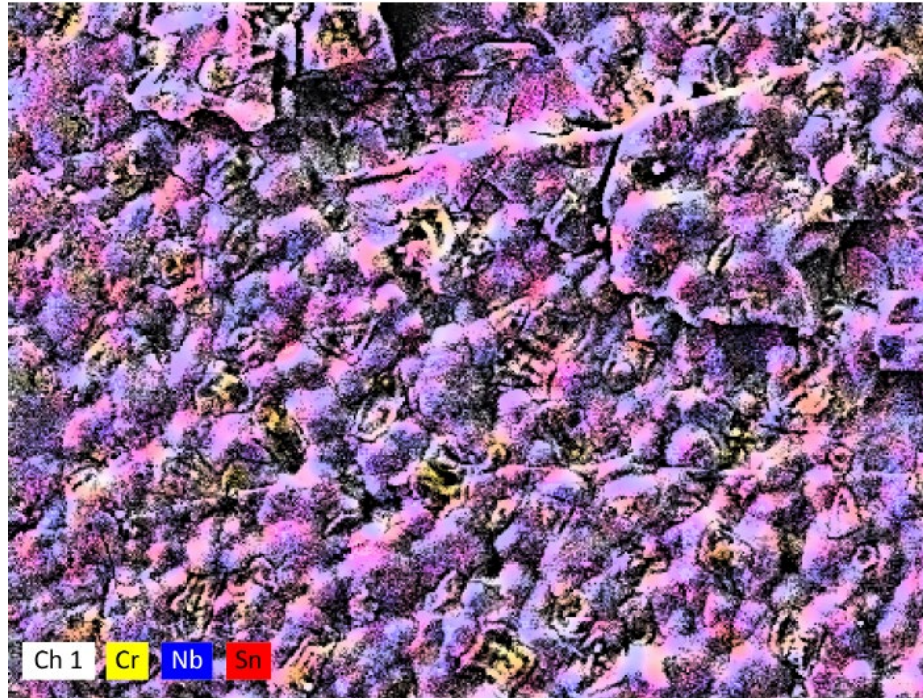
Very good surface

5-10 micron Nb_3Sn thickness



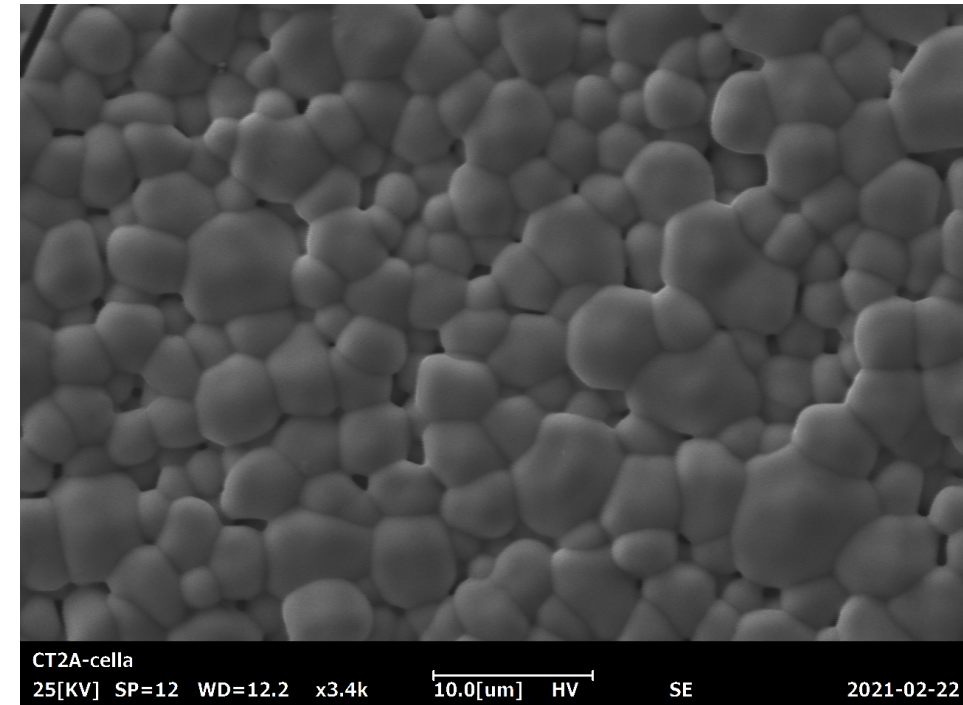
Cr-Ni contamination in 6 GHz cavity

External Surface of a 6 GHz elliptical cavity



Nb 42% Sn 13% **Cr 38%** **Ni 7.2%**

Inner Surface of a 6 GHz elliptical cavity

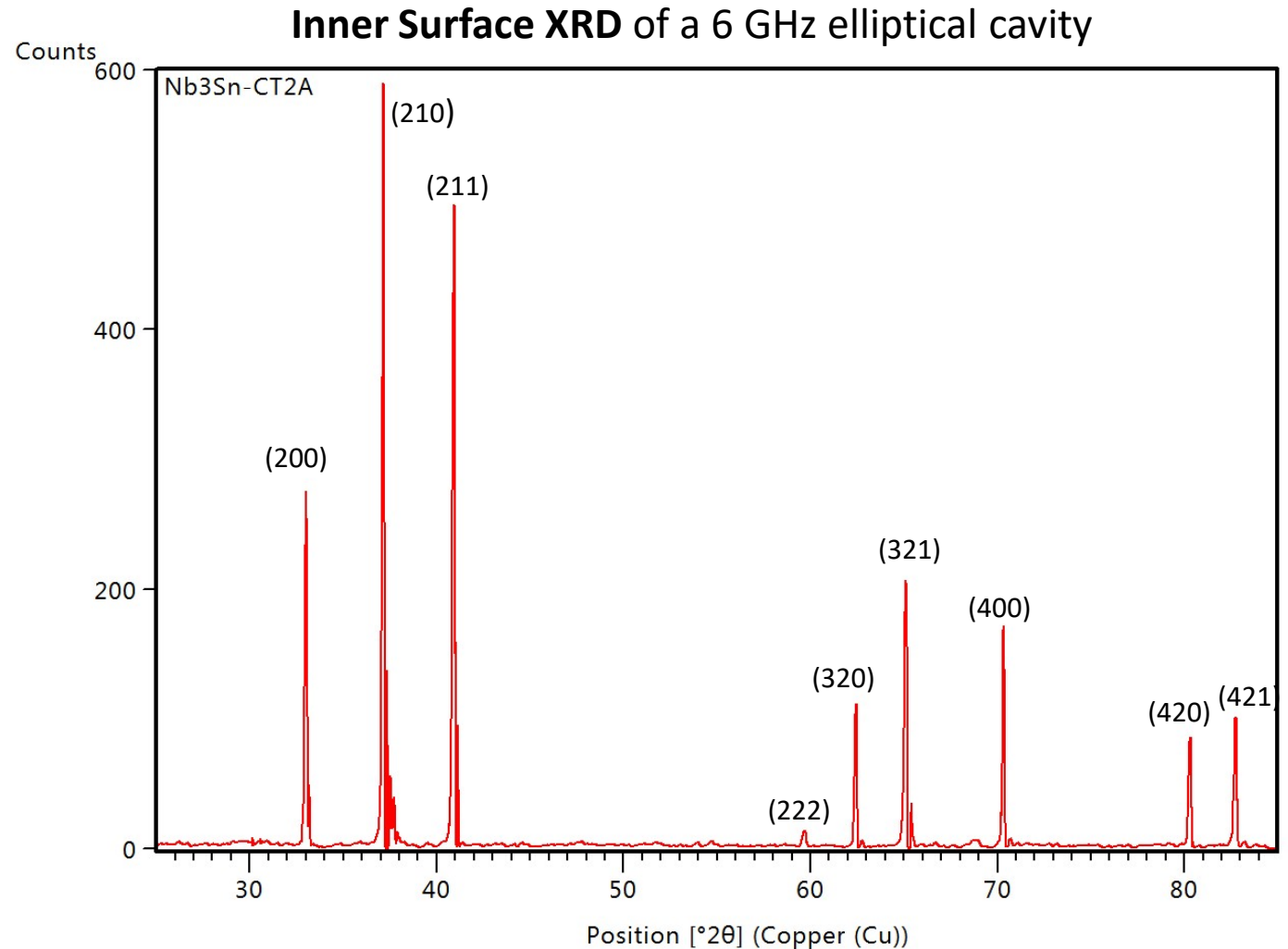


Nb 65% Sn 35% **Cr 0%**

The cavity **geometry preserves** the **inner surface** from **contamination**

6 GHz cavity #1 (only geometry test)

XRD shows only the
Nb₃Sn phase



6 GHz cavity #2



Same process of cavity #1

Problem with upper furnace: annealing at 920 °C instead of 940 °C



45 h of annealing instead of 15 h

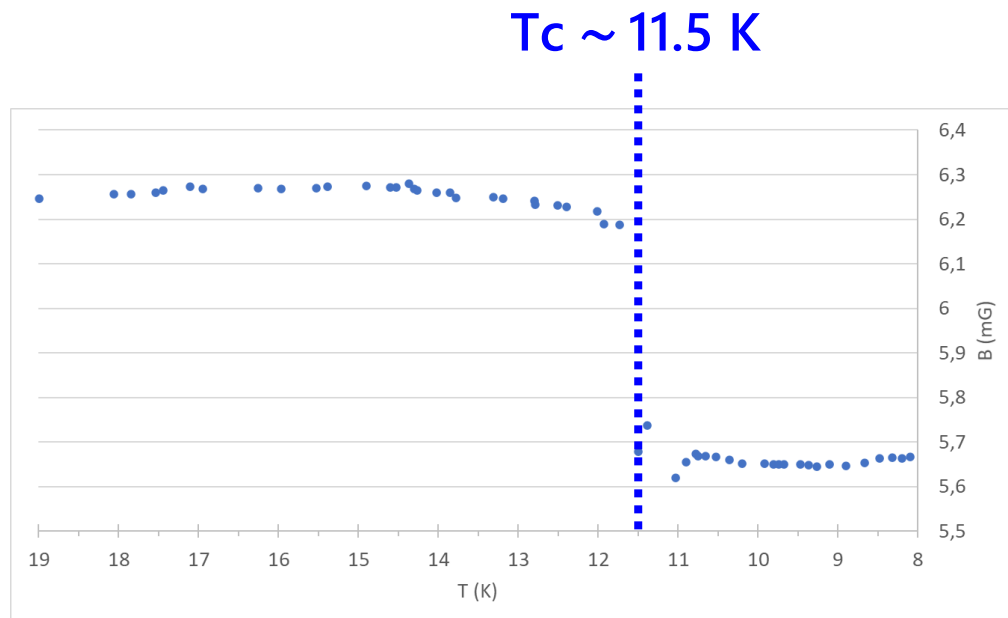


Metallic tin outside

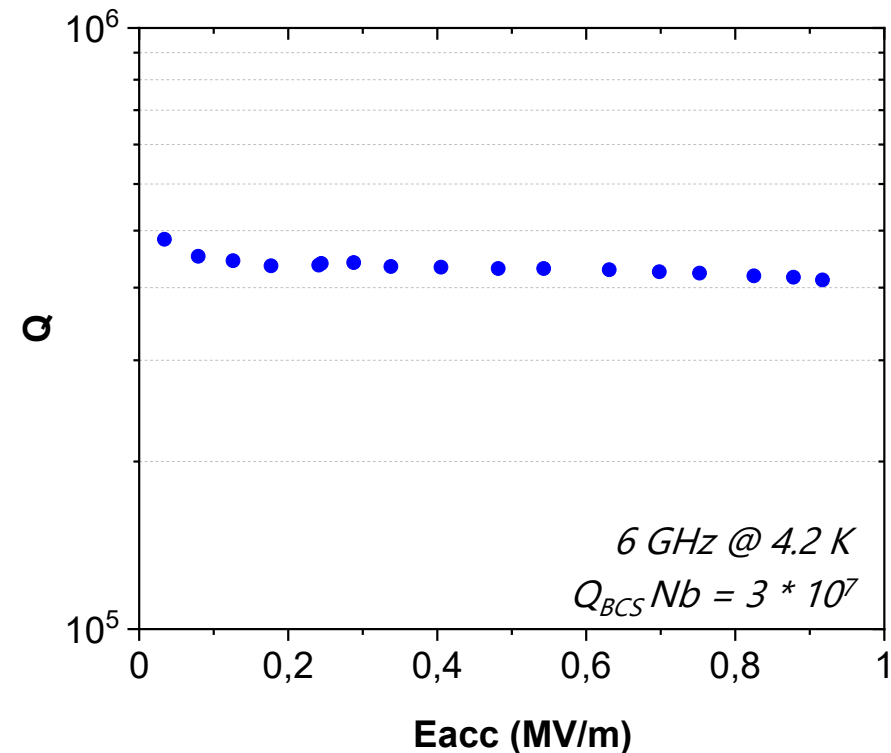
Dark spots in the inner surface

(signs of tin excess)

Tc and RF Test



Flux expulsion measured by a Flux Gate placed in the equator



Poor RF performances comparable to old process

(Sn excess? Cr-Ni contamination? Thick film?)